

Datasheet

LWB5+ M.2

Version 1.3

REVISION HISTORY

Version	Date	Notes	Contributor(s)	Approver
1.0	07 Dec 2020	Initial version	Andrew Chen	Jay White
1.1	01 Feb 2021	Updated Bluetooth v5.0 to v5.2	Sue White	Jonathan Kaye
1.2	03 Mar 2021	Added two Bluetooth current consumption tables	Maggie Teng	Jonathan Kaye
1.3	11 Aug 2021	Added Peak PHY Calibration Current table (Table 18) Added Power-Up Sequence and Timing Requirements	Andrew Chen	Andy Ross

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1 SCOPE

This document describes key hardware aspects of the Laird LWB5+ M.2 module providing either SDIO or USB2.0 interface for WLAN connection and UART/PCM, USB2.0/PCM for Bluetooth® connection. This document is intended to assist device manufacturers and related parties with the integration of this radio into their host devices. Data in this document is drawn from several sources and includes information found in the CYPRESS CYW4373EUBGT data sheet issued in July 2020, along with other documents provided from CYPRESS.

Note that the information in this document is subject to change. Please contact Laird Connectivity to obtain the most recent version of this document.

2 INTRODUCTION

2.1 General Description

The LWB5+ M.2 module is an integrated, M.2 2230 E-Key standard factor, 1x1 SISO with T/R diversity, 802.11 a/b/g/n/ac WLAN plus dual-mode Bluetooth 5.2 Low Energy device that is optimized for low-power mobile devices. The integration of all WLAN and *Bluetooth* functionality in M.2 2230 E-Key standard factor supports low cost and simple implementation along with flexibility for platform-specific customization.

This device is pre-calibrated and integrates the complete transmit/receive RF paths including diplexer, switches, reference crystal oscillator and power management units (PMU). There are two MHF4 connectors on the M.2 board, which can use certified antennas to support antenna diversity. For a list of certified antennas, see [Error! Reference source not found.](#) in the datasheet.

The LWB5+ M.2 module supports IEEE 802.11ac (wave 1) 1x1 SISO with data rates up to MCS9 (433.3 Mbps). Internal Wi-Fi and BT coexistence scheme provides optimized throughput when Wi-Fi and BT are working simultaneously. The device's low power consumption radio architecture and power management unit (PMU) proprietary power save technologies allow for extended battery life.

In addition, its dual 802.11 and Bluetooth radio includes full digital MAC and baseband engines that handle all 802.11 CCK/OFDM® 2.4/5GHz, and Bluetooth 5.2 (Basic Rate, Enhanced Data Rate and Bluetooth Low Energy) baseband and protocol processing.

Please [contact our sales/FAE staff](#) for further information. Ordering information is listed in [Table 1](#).

Table 1: Product ordering information

Order Model	Description
453-00048	802.11ac + Bluetooth 5.2 LWB5+ M.2 Module, SDIO (WLAN) / UART (Bluetooth)
453-00049	802.11ac + Bluetooth 5.2 LWB5+ M.2 Module, USB (WLAN) / USB (Bluetooth)
453-00048-K1	Development Kit for 1x1 802.11ac + Bluetooth 5.2 SDIO/UART M.2 Module
453-00049-K1	Development Kit for 1x1 802.11ac + Bluetooth 5.2 USB/USB M.2 Module

3 LWB5+ M.2 MODULE FEATURES SUMMARY

The Laird LWB5+ M.2 module features are described in [Table 2](#).

Table 2: LWB5+ M.2 module features

Feature	Description
Radio Front End	Integrates the complete transmit/receive diversity RF paths including diplexer, switches, reference crystal oscillator, and power management unit (PMU). Supports 20/40/80MHz channel bandwidth. WLAN/Bluetooth share one antenna.
<p>The <i>Bluetooth</i>® word mark and logos are registered trademarks owned by Bluetooth SIG, Inc. Any use of such marks by Laird is under license. Other trademarks and trade names are those of their respective owners.</p>	
Power Management	One Buck regulator, multiple LDO regulators, and a power management unit (PMU) are integrated into the CYW4373E. All regulators are programmable via the PMU. These blocks simplify power supply design for Bluetooth, and WLAN functions in embedded designs.
Pre-Calibration	RF system tested and calibrated in production
Sleep Clock	An external sleep clock of 32.768 KHz is required
Host Interface Options	<p>The LWB5+ M.2 card provides two interfaces for customers to choose:</p> <ol style="list-style-type: none"> SDIO 1.8V/UART, Wi-Fi section provides support for SDIO v3.0 and also is backward compatible with SDIO v2.0. Bluetooth section supports a high-speed 4-wire UART interface. USB/USB, an on-chip USB 2.0 hub provides a shared single USB connection to both Wi-Fi and Bluetooth target devices.
Advanced WLAN	<ul style="list-style-type: none"> IEEE 802.11ac compliant. Support for MCS8 VHT20 in 20 MHz channels for up to 86.7 Mbps data. Single-stream spatial multiplexing up to 433.3 Mbps data rate. Supports 20, 40, and 80 MHz channels with optional SGI (256 QAM modulation). Full IEEE 802.11a/b/g/n legacy compatibility with enhanced performance. TX and RX low-density parity check (LDPC) support for improved range and power efficiency. On-chip power amplifiers and low-noise amplifiers for both bands. Support wide variety of WLAN encryption: WEP/WPA/TKIP/WPA2 AES-CCMPs
Advanced Bluetooth	<ul style="list-style-type: none"> Qualified for Bluetooth Core Specification 5.2 with all Bluetooth 4.2 optional features <ul style="list-style-type: none"> QDID: Declaration ID: Bluetooth Class 1 or Class 2 transmitter operation. Support data rate: 1 Mbps (GFSK), 2 Mbps ($\pi/4$-DQPSK), 3 Mbps (8-DPSK) Supports extended synchronous connections (eSCO), for enhanced voice quality by allowing for retransmission of dropped packets. Adaptive frequency hopping (AFH) for reducing radio frequency interference. Interface support, host controller interface (HCI) using a highspeed UART interface (or USB interface) and PCM for audio data. Low power consumption improves battery life of IoT and embedded devices. Supports multiple simultaneous Advanced Audio Distribution Profiles (A2DP) for stereo sound. Automatic frequency detection for standard crystal and TCXO values.

4 SPECIFICATIONS

Table 3: Specifications

Feature	Description
Physical Interface	M.2 2230 E-Key standard factor
Wi-Fi Interface	1-bit or 4-bit Secure Digital I/O; USB 2.0
Bluetooth/BLE Interface	Host Controller Interface (HCI) using high speed UART, USB 2.0
Main Chip	Cypress CYW4373EUBGT
Input Voltage Requirements	Typical DC 3.3 V, operating range from DC 3.2V to 3.6V
I/O Signalling Voltage	Compliant with M.2 standard <ul style="list-style-type: none"> For the Key-E form factor, the SDIO, PCM, and UART interfaces only support 1.8V
Operating Temperature	-40° to 85°C (-40° to 185°F)
Operating Humidity	10 to 90% (non-condensing)
Storage Temperature	-40° to 85°C (-40° to 185°F)
Storage Humidity	10 to 90% (non-condensing)
Maximum Electrostatic Discharge	Conductive 4KV; Air coupled 8KV follow EN61000-4-2
Size	30 mm (length) x 22 mm (width) x 3.1 mm (thickness)
Weight	3g
Wi-Fi Media	Direct Sequence-Spread Spectrum (DSSS) Complementary Code Keying (CCK) Orthogonal Frequency Divisional Multiplexing (OFDM)
Bluetooth Media	Frequency Hopping Spread Spectrum (FHSS)
Wi-Fi Multimedia	WMM Wi-Fi Multimedia - PowerSave (WMM-PS with U-APSD) WMM-Sequential Access (WMM-SA with PCF)
Network Architecture Types	Infrastructure and ad-hoc
Wi-Fi Standards	IEEE 802.11a, 802.11b, 802.11e, 802.11g, 802.11h, 802.11i, 802.11k*, 802.11n, 802.11r, 802.11v*, 802.11ac
Bluetooth Standards	Bluetooth 5.2
Wi-Fi Data Rates Supported	Support 802.11 ac/a/b/g/n 1x1 SISO. 802.11b (DSSS, CCK) 1, 2, 5.5, 11 Mbps 802.11a/g (OFDM) 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n (OFDM, HT20/HT40, MCS0-7) 802.11ac (OFDM, VHT20, MCS0-8; OFDM VHT40/VHT80, MCS 0-9)

Feature		Description									
Modulation Table		BPSK, QPSK, CCK, 16-QAM, 64-QAM, and 256-QAM.									
802.11ac	HT	VHT	Spatial Streams	Modulation	Coding	20 MHz		40 MHz		80 MHz	
802.11n	MCS Index	MCS Index				No SGI	SGI	No SGI	SGI	No SGI	SGI
	0	0	1	BPSK	1/2	6.5	7.2	13.5	15	29.3	32.5
	1	1	1	QPSK	1/2	13	14.4	27	30	58.5	65
	2	2	1	QPSK	3/4	19.5	21.7	40.5	45	87.8	97.5
	3	3	1	16-QAM	1/2	26	28.9	54	60	117	130
	4	4	1	16-QAM	3/4	39	43.3	81	90	175.5	195
	5	5	1	64-QAM	2/3	52	57.8	108	120	234	260
	6	6	1	64-QAM	3/4	58.5	65	121.5	135	263.3	292.5
	7	7	1	64-QAM	5/6	65	72.2	135	150	292.5	325
		8	1	256-QAM	3/4	78	86.7	162	180	351	390
		9	1	256-QAM	5/6	N/A	N/A	180	200	390	433.3
802.11ac/n Spatial Streams		1 (1x1 SISO)									
Bluetooth Data Rates Supported		1, 2, 3 Mbps									
Bluetooth Modulation		GFSK@ 1 Mbps Pi/4-DQPSK@ 2 Mbps 8-DPSK@ 3 Mbps									
Regulatory Certifications		USA (FCC) EU – members of European Union (ETSI) Canada Australia Japan									
2.4 GHz Frequency Bands		ETSI: 2.4 GHz to 2.483 GHz FCC/IC: 2.4 GHz to 2.473 GHz MIC: 2.4 GHz to 2.495 GHz RCM: 2.4 GHz to 2.483 GHz									
2.4 GHz Operating Channels (Wi-Fi)		ETSI: 13 (3 non-overlapping) FCC/IC: 11 (3 non-overlapping) MIC: 14 (4 non-overlapping) RCM: 13 (3 non-overlapping)									
5 GHz Frequency Bands		ETSI 5.15 GHz to 5.35 GHz (Ch 36/40/44/48/52/56/60/64) 5.47 GHz to 5.725 GHz (Ch 100/104/108/112/116/120/124/128/132/136/140) 5.725 GHz to 5.85 GHz (Ch 149/153/157/161/165) FCC 5.15 GHz to 5.35 GHz (Ch 36/40/44/48/52/56/60/64) 5.47 GHz to 5.725 GHz (Ch 100/104/108/112/116/120/124/128/132/136/140/144) 5.725 GHz to 5.85 GHz (Ch 149/153/157/161/165) IC 5.15 GHz to 5.35 GHz (Ch 36/40/44/48/52/56/60/64) 5.47 GHz to 5.725 GHz (Ch 100/104/108/112/116/132/136/140/144) 5.725 GHz to 5.85 GHz (Ch 149/153/157/161/165) MIC 5.15 GHz to 5.35 GHz (Ch 36/40/44/48/52/56/60/64) 5.47 GHz to 5.725 GHz (Ch 100/104/108/112/116/120/124/128/132/136/140)									

Feature	Description																																												
	<p>RCM</p> <p>5.15 GHz to 5.35 GHz (Ch 36/40/44/48/52/56/60/64) 5.47 GHz to 5.725 GHz (Ch 100/104/108/112/116/132/136/140) 5.725 GHz to 5.85 GHz (Ch 149/153/157/161/165)</p>																																												
5 GHz Operating Channels (Wi-Fi)	<p>ETSI: 24 non-overlapping; FCC: 25 non-overlapping IC: 22 non-overlapping; MIC: 19 non-overlapping RCM: 21 non-overlapping</p>																																												
Transmit Power	<p>802.11a</p> <table border="0"> <tr> <td>6 Mbps</td> <td>15 dBm (31.6 mW)</td> </tr> <tr> <td>54 Mbps</td> <td>13 dBm (20 mW)</td> </tr> </table> <p>802.11b</p> <table border="0"> <tr> <td>1 Mbps</td> <td>16 dBm (40 mW)</td> </tr> <tr> <td>11 Mbps</td> <td>16 dBm (40 mW)</td> </tr> </table> <p>802.11g</p> <table border="0"> <tr> <td>6 Mbps</td> <td>15.5 dBm (35.5 mW)</td> </tr> <tr> <td>48 Mbps, 54 Mbps</td> <td>14.5 dBm (28.2 mW)</td> </tr> </table> <p>802.11n (2.4 GHz)</p> <table border="0"> <tr> <td>HT20; MCS0-7</td> <td>13.5 dBm (22.4 mW)</td> </tr> <tr> <td>HT40; MCS0-7</td> <td>9.5 dBm (8.9 mW)</td> </tr> </table> <p>802.11n (5 GHz)</p> <table border="0"> <tr> <td>HT20; MCS0-5</td> <td>15 dBm (31.6 mW)</td> </tr> <tr> <td>HT20; MCS6-7</td> <td>13 dBm (20 mW)</td> </tr> <tr> <td>HT40; MCS0-7</td> <td>11 dBm (12.6 mW)</td> </tr> </table> <p>802.11ac (5 GHz)</p> <table border="0"> <tr> <td>VHT20; MCS0-5</td> <td>15 dBm (31.6 mW)</td> </tr> <tr> <td>VHT20; MCS6-7</td> <td>13 dBm (20 mW)</td> </tr> <tr> <td>VHT20; MCS8</td> <td>9.5 dBm (10 mW)</td> </tr> <tr> <td>VHT40; MCS0-7</td> <td>11 dBm (12.6 mW)</td> </tr> <tr> <td>VHT40; MCS8-9</td> <td>9.5 dBm (10 mW)</td> </tr> <tr> <td>VHT80; MCS0-7</td> <td>10 dBm (10 mW)</td> </tr> <tr> <td>VHT80; MCS8-9</td> <td>9 dBm (7.9 mW)</td> </tr> </table> <p>Bluetooth</p> <table border="0"> <tr> <td>1 Mbps (1DH5)</td> <td>7 dBm (5 mW)</td> </tr> <tr> <td>2 Mbps</td> <td>3 dBm (1.99 mW)</td> </tr> <tr> <td>3 Mbps</td> <td>3 dBm (1.99 mW)</td> </tr> <tr> <td>BLE (1 Mbps)</td> <td>7 dBm (5 mW)</td> </tr> </table>	6 Mbps	15 dBm (31.6 mW)	54 Mbps	13 dBm (20 mW)	1 Mbps	16 dBm (40 mW)	11 Mbps	16 dBm (40 mW)	6 Mbps	15.5 dBm (35.5 mW)	48 Mbps, 54 Mbps	14.5 dBm (28.2 mW)	HT20; MCS0-7	13.5 dBm (22.4 mW)	HT40; MCS0-7	9.5 dBm (8.9 mW)	HT20; MCS0-5	15 dBm (31.6 mW)	HT20; MCS6-7	13 dBm (20 mW)	HT40; MCS0-7	11 dBm (12.6 mW)	VHT20; MCS0-5	15 dBm (31.6 mW)	VHT20; MCS6-7	13 dBm (20 mW)	VHT20; MCS8	9.5 dBm (10 mW)	VHT40; MCS0-7	11 dBm (12.6 mW)	VHT40; MCS8-9	9.5 dBm (10 mW)	VHT80; MCS0-7	10 dBm (10 mW)	VHT80; MCS8-9	9 dBm (7.9 mW)	1 Mbps (1DH5)	7 dBm (5 mW)	2 Mbps	3 dBm (1.99 mW)	3 Mbps	3 dBm (1.99 mW)	BLE (1 Mbps)	7 dBm (5 mW)
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BLE (1 Mbps)	7 dBm (5 mW)																																												
Typical Receiver Sensitivity (PER <= 10%)	<p>802.11a:</p> <table border="0"> <tr> <td>6 Mbps</td> <td>-89 dBm</td> </tr> <tr> <td>54 Mbps</td> <td>-73 dBm</td> </tr> </table> <p>802.11b:</p> <table border="0"> <tr> <td>1 Mbps</td> <td>-95 dBm (PER < 8%)</td> </tr> <tr> <td>11 Mbps</td> <td>-88 dBm (PER < 8%)</td> </tr> </table> <p>802.11g:</p> <table border="0"> <tr> <td>6 Mbps</td> <td>-92 dBm</td> </tr> <tr> <td>54 Mbps</td> <td>-75 dBm</td> </tr> </table> <p>802.11n (2.4 GHz)</p> <table border="0"> <tr> <td>6.5 Mbps (MCS0; HT20)</td> <td>-92 dBm</td> </tr> <tr> <td>65 Mbps (MCS7; HT20)</td> <td>-73 dBm</td> </tr> <tr> <td>13.5 Mbps (MCS0; HT40)</td> <td>-89 dBm</td> </tr> </table>	6 Mbps	-89 dBm	54 Mbps	-73 dBm	1 Mbps	-95 dBm (PER < 8%)	11 Mbps	-88 dBm (PER < 8%)	6 Mbps	-92 dBm	54 Mbps	-75 dBm	6.5 Mbps (MCS0; HT20)	-92 dBm	65 Mbps (MCS7; HT20)	-73 dBm	13.5 Mbps (MCS0; HT40)	-89 dBm																										
6 Mbps	-89 dBm																																												
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65 Mbps (MCS7; HT20)	-73 dBm																																												
13.5 Mbps (MCS0; HT40)	-89 dBm																																												
Note: Transmit power on each channel varies per individual country regulations. All values are nominal with +/-2 dBm tolerance at room temperature. Tolerance could be up to +/-2.5 dBm across operating temperature.																																													
Note: HT20 – 20 MHz-wide channels HT40 – 40 MHz-wide channels HT80 – 80 MHz-wide channels																																													
Note: All values nominal, +/-3 dBm.																																													

Feature	Description
	135 Mbps (MCS7; HT40) -70 dBm
	802.11n (5 GHz)
	6.5 Mbps (MCS0; HT20) -89 dBm
	65 Mbps (MCS7; HT20) -70 dBm
	13.5Mbps (MCS0; HT40) -86 dBm
	135Mbps (MCS7; HT40) -66 dBm
	802.11ac (5 GHz)
	6.5 Mbps (MCS0; VHT20) -88 dBm
	78 Mbps (MCS8; VHT20) -66 dBm
	13.5 Mbps (MCS0; VHT40) -86 dBm
	180 Mbps (MCS9; VHT40) -62 dBm
	29.3 Mbps (MCS0; VHT80) -83 dBm
	390 Mbps (MCS9; VHT80) -59 dBm
	Bluetooth:
	1 Mbps (1DH5) -90 dBm
	2 Mbps (2DH5) -92 dBm
	3 Mbps (3DH5) -86 dBm
	Bluetooth LE -93 dBm
Operating Systems Supported	Linux Android
Security	<ul style="list-style-type: none"> ▪ WEP ▪ WPA and WPA2 (Personal) support for powerful encryption and authentication. ▪ AES and TKIP in hardware for faster data encryption and IEEE 802.11i compatibility. ▪ Reference WLAN subsystem provides Wi-Fi Protected Setup (WPS). ▪ CKIP
Compliance	<p>ETSI Regulatory Domain EN 300 328 EN 301 489-1 EN 301 489-17 EN 301 893 EN 60950-1 2011/65/EU (RoHS)</p> <p>FCC Regulatory Domain FCC 15.247 DTS – 802.11b/g (Wi-Fi) – 2.4 GHz FCC 15.407 UNII – 802.11a (Wi-Fi) – 5 GHz FCC 15.247 DSS – BT 2.1</p> <p>Industry Canada RSS-247 – 802.11a/b/g/n (Wi-Fi) – 2.4 GHz, 5.8 GHz, 5.2 GHz, and 5.4 GHz RSS-247 – BT 2.1</p> <p>RCM AS/NZS 4268 :2017 AS/NZS 4268 DFS</p> <p>MIC Japan ARIB STD-T66/-33/-T71</p>
Certifications (Pending)	Bluetooth® SIG Qualification
Warranty	One Year Warranty

All specifications are subject to change without notice

5 WLAN FUNCTIONAL DESCRIPTION

5.1 Overview

The LWB5+ M.2 module is designed based on the CYPRESS CYW4373EUBGT 802.11ac/a/b/g/n chipset. It is optimized for high speed, reliable, and low-power embedded applications. It's integrated with dual-band WLAN (2.4/5GHz) and Bluetooth 5.2. Its functionality includes:

- Improved throughput on the link due to frame aggregation, RIFS (reduced inter-frame spacing), and half guard intervals.
- Support for LDPC (Low Density Parity Check) codes.
- Improved 11n performance due to features such as 11n frame aggregation (TX A-MPDU) and low-overhead host-assisted buffering (RX A-MPDU). These techniques can improve performance and efficiency of applications involving large bulk data transfers such as file transfers or high-resolution video streaming.
- IEEE 802.11ac, 1x1 SISO with data rate up to MCS9 (433.3Mbps).

Additional functionality is listed in the following table (Table 4).

Table 4: WLAN functions

Feature	Description
WLAN MAC	<ul style="list-style-type: none"> ▪ Enhanced MAC for supporting IEEE 802.11ac features ▪ Transmission and reception of aggregated MPDUs (A-MPDUs) for very high throughput (VHT) ▪ Support for power management schemes, including WMM power-save, power-save multi-poll (PSMP) and multiphase PSMP operation ▪ Support for immediate ACK and Block-ACK policies ▪ Interframe space timing support, including RIFS ▪ Support for RTS/CTS and CTS-to-self frame sequences for protecting frame exchanges ▪ Back-off counters in hardware for supporting multiple priorities as specified in the WMM specification ▪ Timing synchronization function (TSF), network allocation vector (NAV) maintenance, and target beacon transmission time (TBTT) ▪ generation in hardware and capturing the TSF timer on an external time synchronization pulse ▪ Hardware offload for AES-CCMP, legacy WPA TKIP, legacy WEP ciphers, WAPI, and support for key management ▪ Support for coexistence with Bluetooth and other external radios ▪ Programmable independent basic service set (IBSS) or infrastructure basic service set functionality ▪ Statistics counters for MIB support
WLAN Security	<ul style="list-style-type: none"> ▪ WLAN Encryption features supported include: <ul style="list-style-type: none"> – Temporal Key Integrity Protocol (TKIP)/Wired Equivalent Privacy (WEP) – Advanced Encryption Standard (AES)/Counter-Mode/CBC-MAC Protocol (CCMP) – WLAN Authentication and Private Infrastructure (WPAI)

Feature	Description
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WLAN Channel Channel frequency supported.

20 MHz		40 MHz		80 MHz			
Channel	Freq. (MHz)	Channel	Freq. (MHz)	Channel	Freq. (MHz)		
1	2412	36	5180	1-5	2422	42	5210
2	2417	40	5200	2-6	2427	58	5290
3	2422	44	5220	3-7	2432	74	5370
4	2427	48	5240	4-8	2437	90	5410
5	2432	52	5260	5-9	2442	106	5530
6	2437	56	5280	6-10	2447	122	5610
7	2442	60	5300	7-11	2452	138	5690
8	2447	64	5320	36-40	5190	155	5775
9	2452	100	5500	44-48	5230		
10	2457	104	5520	52-56	5270		
11	2462	108	5540	60-64	5310		
12	2467	112	5560	68-72	5350		
13	2472	116	5580	76-80	5390		
		120	5600	84-88	5430		
		124	5620	92-96	5470		
		128	5640	100-104	5510		
		132	5660	108-112	5550		
		136	5680	116-120	5590		
		140	5700	124-128	5630		
		144	5720	132-136	5670		
		149	5745	140-144	5710		
		153	5765	149-153	5755		
		157	5785	157-161	5795		
		161	5805				
		165	5825				

6 BLUETOOTH FUNCTIONAL DESCRIPTION

The LWB5+ M.2 module includes a fully-integrated Bluetooth baseband/radio. Several features and functions are listed in Table 5.

Table 5: Bluetooth functions

Feature	Description
Bluetooth Interface	<ul style="list-style-type: none"> ▪ Voice interface: <ul style="list-style-type: none"> – Hardware support for continual PCM data transmission/reception without processor overhead. – Standard PCM clock rates from 64 kHz to 2.048 MHz with multi-slot handshake and synchronization. – A-law, U-law, and linear voice PCM encoding/decoding. ▪ High-Speed UART interface ▪ USB 2.0
Bluetooth Core functionality	<ul style="list-style-type: none"> ▪ Bluetooth 5.2 Core Spec (errata) ▪ Bluetooth Class 2/Bluetooth class 1 ▪ WLAN and Bluetooth share same LNA and antenna ▪ Digital audio interfaces with TDM interface for voice application ▪ Baseband and radio BDR and EDR package type: 1 Mbps, 2 Mbps, 3 Mbps ▪ Fully functional Bluetooth baseband: AFH, forward error correction, header error control, access code correction, CRC, encryption bit stream generation, and whitening. ▪ Adaptive Frequency Hopping (AFH) using Packet Error Rate (PER) ▪ Interlaced scan for faster connection setup ▪ Simultaneous active ACL connection setup ▪ Automatic ACL package type selection ▪ Full master and slave piconet support ▪ Scatter net support ▪ SCO/eSCO links with hardware accelerated audio signal processing and hardware supported PPEC algorithm for speech quality improvement ▪ All standard SCO/eSCO voice coding ▪ All standard pairing, authentication, link key, and encryption operations ▪ Encryption (AES) support
Bluetooth Low Energy (BLE) Core functionality	<ul style="list-style-type: none"> ▪ Bluetooth 5.2 Core Spec (Errata) ▪ Bluetooth 4.2 Features: <ul style="list-style-type: none"> – LE privacy 1.2 – LE Secure Connection. – LE Data Length Extension ▪ Bluetooth 4.0 Features: <ul style="list-style-type: none"> – Advertiser, Scanner, Initiator, Master, and Slave roles support (connects to 16 links) – WLAN/Bluetooth Coexistence (BCA) protocol support. – Shared RF with BDR/EDR – Encryption (AES) support. – Intelligent Adaptive Frequency Hopping (AFH)

7 BLOCK DIAGRAM

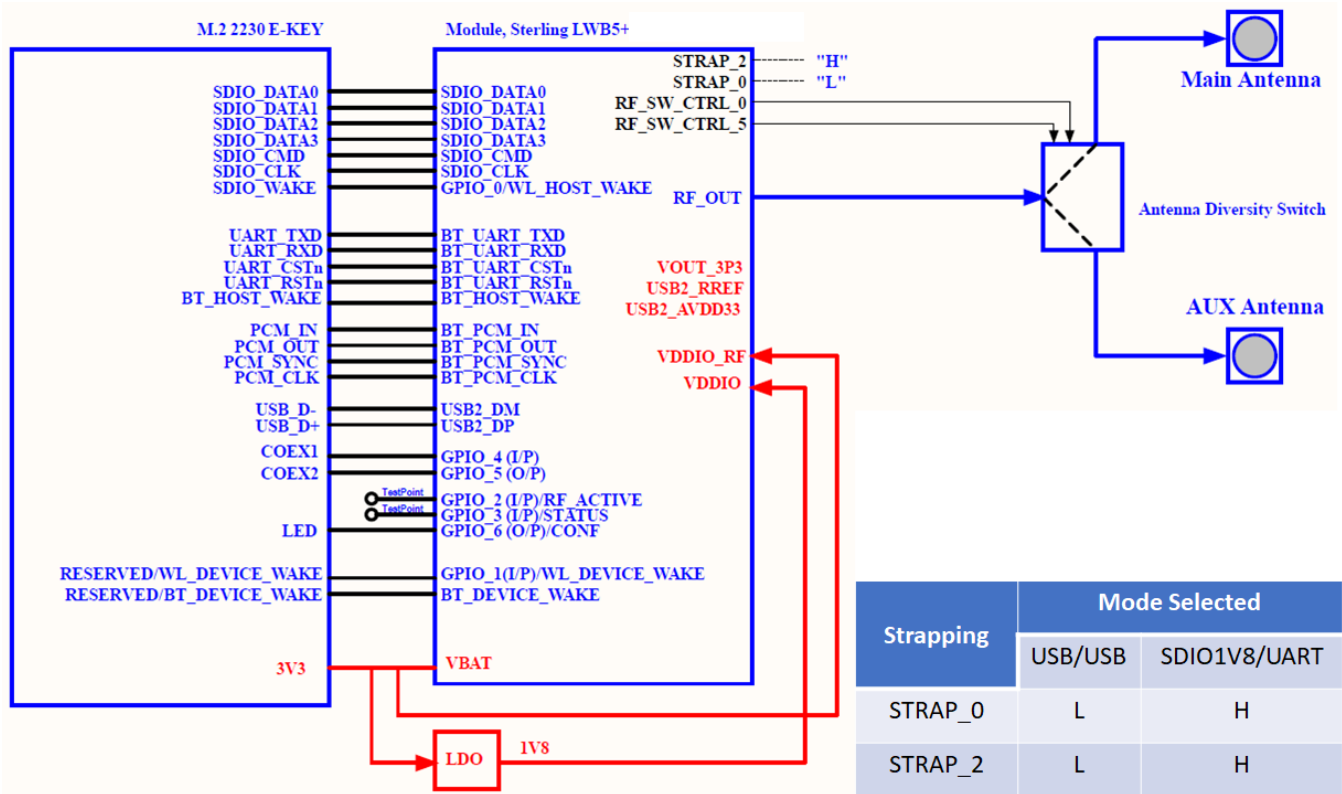


Figure 1: Block diagram

8 ELECTRICAL CHARACTERISTICS

8.1 Absolute Maximum Ratings

Table 6 summarizes the absolute maximum ratings and Table 7 lists the recommended operating conditions for the LWB5+ M.2 module. Absolute maximum ratings are those values beyond which damage to the device can occur. Functional operation under these conditions, or at any other condition beyond those indicated in the operational sections of this document, is not recommended.

Note: Maximum rating for signals follows the supply domain of the signals.

Table 6: Absolute maximum ratings

Symbol (Domain)	Parameter	Max Rating	Unit
3V3	External 3.3V power supply	4.0	V
Storage	Storage Temperature	-40 to +85	°C
Antenna	Maximum RF input (reference to 50-Ω input)	+10	dBm
ESD	Electrostatic discharge tolerance	2000	V

8.2 Recommended Operating Conditions

Table 7: Recommended Operating Conditions

Symbol (Domain)	Parameter	Min	Typ	Max	Unit
3V3	External 3.3V power supply	3.2	3.30	3.6	V
T-ambient	Ambient temperature	-40	25	85	°C

8.3 DC Electrical Characteristics

Table 8 list the general DC electrical characteristics over recommended operating conditions (unless otherwise specified).

Table 8: General DC electrical characteristics (For 1.8V operation VDDIO; VIO_SD)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
VIH	High Level Input Voltage	—	1.17	—	—	V
VIL	Low Level Input Voltage	—	—	—	0.63	V
VOH	Output high Voltage	—	1.35	—	—	V
VOL	Output low Voltage	—	—	—	0.45	V

8.4 WLAN Radio Receiver Characteristics

Table 9 and Table 10 summarize the LWB5+ M.2 module receiver characteristics.

Table 9: WLAN receiver characteristics for 2.4 GHz

Symbol	Parameter	Min	Typ	Max	Unit
Fr _x	Receive input frequency range	2.412	—	2.484	GHz
Sr _f					
	CCK, 1 Mbps	—	-95	—	dBm
	CCK, 11 Mbps	—	-88	—	
	OFDM, 6 Mbps	—	-92	—	
	OFDM, 54 Mbps	—	-75	—	
	HT20, MCS0	—	-92	—	
	HT20, MCS7	—	-73	—	
	HT40, MCS0	—	-89	—	
	HT40, MCS7	—	-70	—	
Radj					
	OFDM, 6 Mbps	16	38	—	dB
	OFDM, 54 Mbps	-1	20.4	—	
	HT20, MCS0	16	33.3	—	
	HT20, MCS7	-2	13.7	—	

Table 10: WLAN Receiver Characteristics for 5 GHz

Symbol	Parameter	Min	Typ	Max	Unit
Fr _x	Receive input frequency range	5.15	—	5.825	GHz
Sr _f					
	OFDM, 6 Mbps	—	-89	—	dBm

Symbol	Parameter	Min	Typ	Max	Unit
	OFDM, 54 Mbps	—	-73	—	
	HT20, MCS0	—	-89	—	
	HT20, MCS7	—	-70	—	
	HT40, MCS0	—	-86	—	
	HT40, MCS7	—	-66	—	
	VHT20, MCS0	—	-88	—	
	VHT20, MCS8	—	-66	—	
	VHT40, MCS0	—	-86	—	
	VHT40, MCS9	—	-62	—	
	VHT80, MCS0	—	-83	—	
VHT80, MCS9	—	-59	—		
Radj (Difference between interfering and desired signal (20 MHz apart))	OFDM, 6 Mbps	16	31.7	—	dB
	OFDM, 54 Mbps	-1	13.8	—	
	OFDM, 65 Mbps	-2	8.4	—	
Radj. (Difference between interfering and desired signal (40 MHz apart))	OFDM, 6 Mbps	32	44.7	—	dB
	OFDM, 54 Mbps	15	26.6	—	
	OFDM, 65 Mbps	14	26.8	—	

8.5 WLAN Transmitter Characteristics

Table 11: WLAN transmitter characteristics for 2.4 GHz operation (SDIO=VDIO=1.8V)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Ftx	Transmit output frequency range	—	2.412	—	2.484	GHz
Pout	11b mask compliant	1-11 Mbps	—	18	—	dBm
	11g mask compliant	6-36 Mbps	—	17.5	—	
	11g EVM compliant	48-54 Mbps	—	16.5	—	
	11n HT20 mask compliant	MCS 0-5	—	15.5	—	
	11n HT20 EVM compliant	MCS 6-7	—	15.5	—	
	11n HT40 mask compliant	MCS 0-5	—	11.5	—	
	11n HT40 EVM compliant	MCS 6-7	—	11.5	—	
ATx	Transmit power accuracy at 25 °C	—	-2.0	—	+2.0	dB

Freq.	Mode/Rate (Mbps)	Output Power (dBm)	Maximum Current Consumption	
			(mA)	
2412 MHz	1 Mbps	18 dBm	390	
	11 Mbps	18 dBm	406	
	6 Mbps	17.5 dBm	406	
	54 Mbps	16.5 dBm	364	

Freq.	Mode/Rate (Mbps)	Output Power (dBm)	Maximum Current Consumption (mA)
2442 MHz	HT20 MCS 0	15.5 dBm	361
	HT20 MCS 7	15.5 dBm	339
	HT40 MCS 0	11.5 dBm	324
	HT40 MCS 7	11.5 dBm	298
	1 Mbps	18 dBm	390
	11 Mbps	18 dBm	406
	6 Mbps	17.5 dBm	406
	54 Mbps	16.5 dBm	364
2472 MHz	HT20 MCS 0	15.5 dBm	361
	HT20 MCS 7	15.5 dBm	339
	HT40 MCS 0	11.5 dBm	324
	HT40 MCS 7	11.5 dBm	298
	1 Mbps	18 dBm	390
	11 Mbps	18 dBm	406
	6 Mbps	17.5 dBm	406
	54 Mbps	16.5 dBm	364
2472 MHz	HT20 MCS 0	15.5 dBm	361
	HT20 MCS 7	15.5 dBm	339
	HT40 MCS 0	11.5 dBm	324
	HT40 MCS 7	11.5 dBm	298
	1 Mbps	18 dBm	390
	11 Mbps	18 dBm	406
	6 Mbps	17.5 dBm	406
	54 Mbps	16.5 dBm	364

Table 12: WLAN transmitter characteristics for 5 GHz operation (SDIO=VDIO=1.8V)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Ftx	Transmit output frequency range	—	5.15	—	5.925	GHz
Pout	Output power	See Note ²	—	—	—	—
	11a mask compliant	6-48 Mbps	—	17	—	dBm
	11a EVM compliant	54 Mbps	—	15	—	
	11n HT20 mask compliant	MCS 0-5	—	17	—	
	11n HT20 EVM compliant	MCS 6-7	—	15	—	
	11n HT40 mask compliant	MCS 0-5	—	13	—	
	11n HT40 EVM compliant	MCS 6-7	—	13	—	
	11ac VHT20 mask compliant	MCS 0-5	—	17	—	
	11ac VHT20 EVM compliant	MCS 6-7	—	15	—	
	11ac VHT20 EVM compliant	MCS 8	—	11.5	—	
	11ac VHT40 mask compliant	MCS 0-5	—	13	—	
	11ac VHT40 EVM compliant	MCS 6-7	—	13	—	
	11ac VHT40 EVM compliant	MCS 8-9	—	11.5	—	
	11ac VHT80 mask compliant	MCS 0-5	—	12	—	

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
	11ac VHT80 EVM compliant	MCS 6-7	—	12	—	
	11ac VHT80 EVM compliant	MCS 8-9	—	11	—	
ATx	Transmit power accuracy at 25 °C	—	-2.0	—	+2.0	dB

Table 13: WLAN current consumption on 5 GHz (SDIO=VDIO=1.8V)

Freq.	Mode/Rate [Mbps]	Output Power Per Chain [dBm]	Maximum Current Consumption
			(mA)
5180 MHz	6 Mbps	17 dBm	378
	54 Mbps	15 dBm	341
	HT20 MCS 0	17 dBm	382
	HT20 MCS 7	15 dBm	352
5190 MHz	HT40 MCS 0	13 dBm	367
	HT40 MCS 7	13 dBm	354
5210 MHz	VHT80 MCS 0	12 dBm	391
	VHT80 MCS 9	11 dBm	339
5500 MHz	6 Mbps	17 dBm	378
	54 Mbps	15 dBm	341
	HT20 MCS 0	17 dBm	382
	HT20 MCS 7	15 dBm	352
5510 MHz	HT40 MCS 0	13 dBm	367
	HT40 MCS 7	13 dBm	354
5530 MHz	VHT80 MCS 0	12 dBm	391
	VHT80 MCS 9	11 dBm	339
5825 MHz	6 Mbps	17 dBm	378
	54 Mbps	15 dBm	341
	HT20 MCS 0	17 dBm	382
	HT20 MCS 7	15 dBm	352
5795 MHz	HT40 MCS 0	13 dBm	367
	HT40 MCS 0	13 dBm	354
5775 MHz	VHT80 MCS 0	12 dBm	391
	VHT80 MCS 9	11 dBm	339

Note: Final TX power values on each channel are limited by regulatory requirements

9 BLUETOOTH RADIO CHARACTERISTICS

Table 14 through Table 16 describe the basic rate transmitter performance, basic rate receiver performance, enhanced rate receiver performance, and current consumption conditions at 25°C.

Table 14: Basic rate transmitter performance temperature at 25°C (3.3V)

Test Parameter	Min	Typ	Max	BT Spec.	Unit	
Maximum RF Output Power	GFSK	—	—	7	0 ~ +20	dBm
	$\pi/4$ -DQPSK	—	3	—		
	8-DPSK	—	3	—		
Frequency Range	2.4	—	2.4835	$2.4 \leq f \leq 2.4835$	GHz	
20 dB Bandwidth	—	919.5	—	≤ 1000	KHz	
Δf_{1avg} Maximum Modulation	140	155	175	$140 < \Delta f_{1avg} < 175$	KHz	
Δf_{2max} Minimum Modulation	115	135	—	≥ 115	KHz	
$\Delta f_{2avg}/\Delta f_{1avg}$	—	0.9	—	≥ 0.80	—	
Initial Carrier Frequency	—	± 25	± 75	$\leq \pm 75$	KHz	
Frequency Drift (DH1 packet)	—	± 10	± 25	± 25	KHz	
Frequency Drift (DH3 packet)	—	± 10	± 40	± 40	KHz	
Frequency Drift (DH5 packet)	—	± 10	± 40	± 40	KHz	
Drift rate	—	8	20	20	KHz/50us	
Adjacent Channel Power	$F \geq \pm 3$ MHz	—	-50	—	< -40	dBm
	$F = \pm 2$ MHz	—	-46	—	≤ -20	dBm
	$F = \pm 1$ MHz	—	-15	—	N/A	dBm

Table 15: Basic rate receiver performance at 3.3V

Test Parameter	Min	Typ	Max	BT Spec.	Unit	
Sensitivity (1DH5) BER $\leq 0.1\%$	—	-90	—	≤ -70	dBm	
Maximum Input BER $\leq 0.1\%$	—	—	-20	≥ -20	dBm	
Interference Performance	Co-Channel	—	9	11	11	dB
	C/I 1 MHz adjacent channel	—	-5.5	0	0	dB
	C/I 2 MHz adjacent channel	—	-38	-30	-30	dB
	C/I ≥ 3 MHz adjacent channel	—	-46	-40	-40	dB
	C/I image channel	—	-25.5	-9	-9	dB
C/I 1-MHz adjacent to image channel	—	-39	-20	-20	dB	

Table 16: Enhanced data rate receiver performance (3.3V)

Test Parameter	Min	Typ	Max	BT Spec.	Unit	
Sensitivity (BER $\leq 0.01\%$)	$\pi/4$ -DQPSK	—	-92	—	≤ -70	dBm
	8-DPSK	—	-86	—	≤ -70	dBm
Maximum Input (BER $\leq 0.1\%$)	$\pi/4$ -DQPSK	—	—	-20	≥ -20	dBm
	8-DPSK	—	—	-20	≥ -20	dBm
C/I Co-Channel (BER $\leq 0.1\%$)	$\pi/4$ -DQPSK	—	10.5	13	$\leq \pm 13$	dB
	8-DPSK	—	17.5	21	$\leq \pm 21$	dB

Test Parameter		Min	Typ	Max	BT Spec.	Unit
C/I 1 MHz adjacent Channel	π/4-DQPSK	—	-6	0	≤ 0	dB
	8-DPSK	—	-3	5	≤5	dB
C/I 2 MHz adjacent Channel	π/4-DQPSK	—	-38.5	-30	≤ -30	dB
	8-DPSK	—	-37.5	-25	≤ -25	dB
C/I ≥ 3 MHz adjacent Channel	π/4-DQPSK	—	-47	-40	≤ -40	dB
	8-DPSK	—	-39.5	-33	≤ -33	dB
C/I image channel	π/4-DQPSK	—	-24.5	-7	≤ -7	dB
	8-DPSK	—	-17	0	≤ 0	dB
C/I 1 MHz adjacent to image channel	π/4-DQPSK	—	-43	-20	≤ -20	dB
	8-DPSK	—	-37	-13	≤ -13	dB
Out-of-Band Blocking Performance (CW) BER ≤ 0.1%	30-2000MHz	—	-10	—	—	dBm
	2-2.399GHz	—	-27	—	—	dBm
	2.484-3GHz	—	-27	—	—	dBm
	3-12.75GHz	—	-10	—	—	dBm

Table 17: BLE RF Specifications (3.3V)

Parameter	Conditions	Min	Typ	Max	Unit
Frequency range	—	2402	—	2480	MHz
Rx sensitivity ³	GFSK, 30.8% PER, 1Mbps	—	-93	—	dBm
Tx power ⁴	—	—	—	7	dBm
Δf1 average	—	225	255	275	KHz
Δf2 maximum ⁵	—	185	220	—	KHz
$\frac{\Delta f2_{avg}}{\Delta f1_{avg}}$ ratio	—	0.8	0.95	—	—

Notes

[3] Dirty Tx is Off.

[4] The BLE TX power cannot exceed 10 dBm EIRP specification limit. The front-end losses and antenna gain/loss must be factored in so as not to exceed the limit.

[5] At least 99.9% of all Δf2 maximum frequency values recorded over 10 packets must be greater than 185 KHz.

Table 18: Bluetooth current consumption, VBAT=VDDIO=3.3V

Operating Mode	Tx	Rx	Unit
DH1	24.07	24.06	mA
DH3	29.23	29.03	mA
DH5	30.04	30.02	mA
2DH1	18.24	18.19	mA
2DH3	25.46	25.12	mA
2DH5	25.83	25.77	mA

Operating Mode	Tx	Rx	Unit
3DH1	21.47	21.43	mA
3DH3	25.21	25.26	mA
3DH5	25.84	25.79	mA
LE	30.37	14.61	mA

Table 19: Bluetooth current consumption, VBAT=3.3V, VDDIO=1.8V

Operating Mode	Tx	Rx	Unit
DH1	23.62	23.57	mA
DH3	28.57	28.54	mA
DH5	29.62	29.62	mA
2DH1	17.65	17.77	mA
2DH3	24.06	24.07	mA
2DH5	25.11	25.12	mA
3DH1	20.91	20.87	mA
3DH3	24.42	24.72	mA
3DH5	25.34	25.29	mA
LE	30.04	14.19	mA

Table 20: Peak PHY Calibration Current

Mode	V _{BAT} = 3.3V V _{DDIO} = 1.8V T _A = 25°C	
	V _{BAT} , mA	V _{IO} , µA
Unassociated (2.4 GHz)	768	510
Associated (2.4 GHz)	748	560
Unassociated (5 GHz)	666	410
Associated (5 GHz)	664	390

10 HOST INTERFACE SPECIFICATIONS

10.1 SDIO Specifications

The LWB5+ M.2 module SDIO host interface pins are powered from the VIO_SD voltage supply, which is set internally at 1.8V on the M.2 module. The SDIO electrical specifications are identical for the 1-bit SDIO and 4-bit SDIO modes.

Note: The SDIO host signals must be 1.8v at all times as defined by the M.2 standard.

10.1.1 Default Speed, High-speed Modes

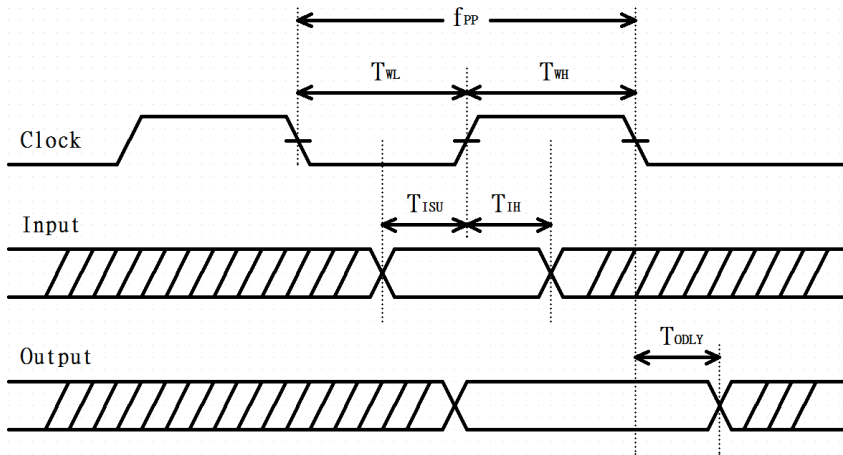


Figure 2: SDIO protocol timing diagram--- default mode (1.8V)

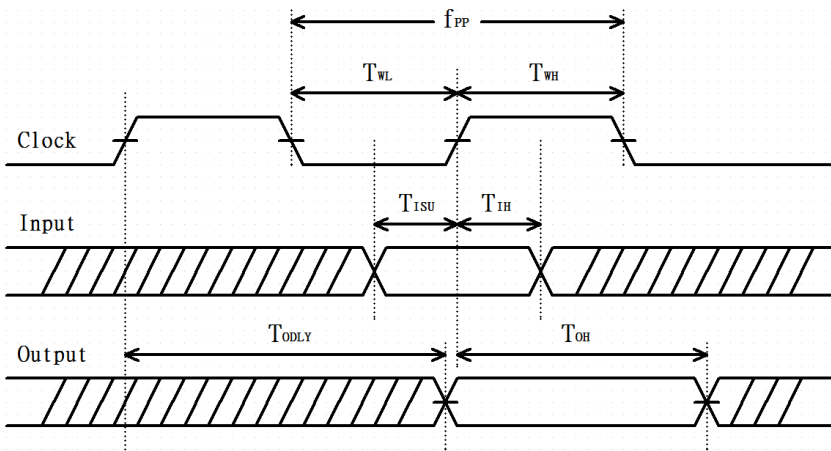


Figure 3: SDIO protocol timing diagram--- High-Speed mode (1.8V)

Note: Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

Table 21: SDIO timing requirements

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
f _{PP}	Clock Frequency	Default Speed	0	-	25	MHz
		High-Speed	0	-	50	

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
TWL	Clock low time	Default Speed	10	-	-	ns
		High-Speed	7	-	-	
TWH	Clock high time	Default Speed	10	-	-	ns
		High-Speed	7	-	-	
TISU	Input Setup time	Default Speed	5	-	-	ns
		High-Speed	6	-	-	
TIH	Input Hold time	Default Speed	5	-	-	ns
		High-Speed	2	-	-	
TODLY	Output delay time CL ≤ 40pF (1 card)	Default Speed	-	-	14	ns
		High-Speed	-	-	14	
TOH	Output hold time	High-Speed	0	-	-	ns

10.1.2 SDR12, SDR25, SDR50 Mode (up to 100MHz) (1.8V)

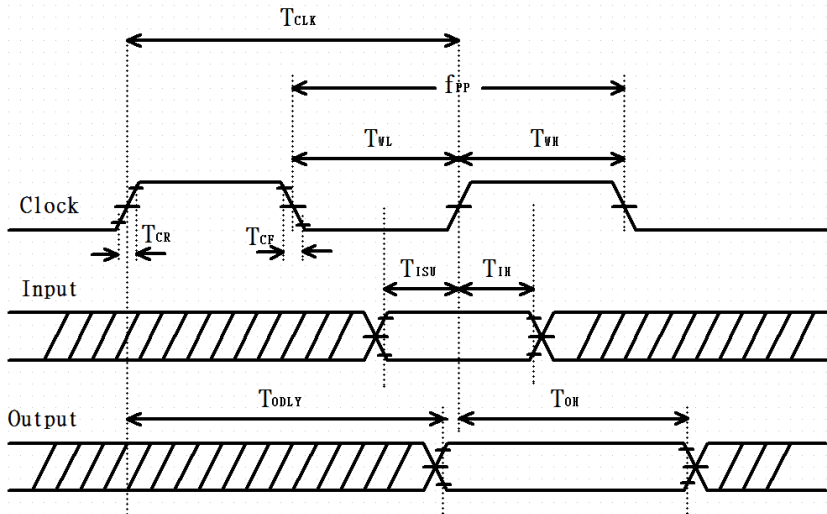


Figure 4: SDIO protocol timing Diagram--- SDR12, SDR25, SDR50 modes (up to 100 MHz) (1.8V)

Note: Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

Table 22: SDIO timing requirements--- SDR12, SDR25, SDR50 modes (up to 100 MHz) (1.8V)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
fPP	Clock Frequency	SDR12/25/50	25	-	100	MHz
TISU	Input setup time	SDR12/25/50	3	--	-	ns
TIH	Input Hold time	SDR12/25/50	0.8	-	-	ns
TCLK	Clock Time	SDR12/25/50	10	-	40	ns
TCR, TCF	Raise time, Fall time	SDR12/25/50	-	-	0.2*TCLK	ns
	TCR, TCF <2ns (max) at 100MHz CCARD=10pF					
TODLY	Output delay time CL ≤ 30pF	SDR12/25/50	-	-	7.5	ns

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
TOH	Output hold time CL=15pF	SDR12/25/50	1.5	-	-	ns

10.1.3 SDR104 Mode (208 MHz) (1.8V)

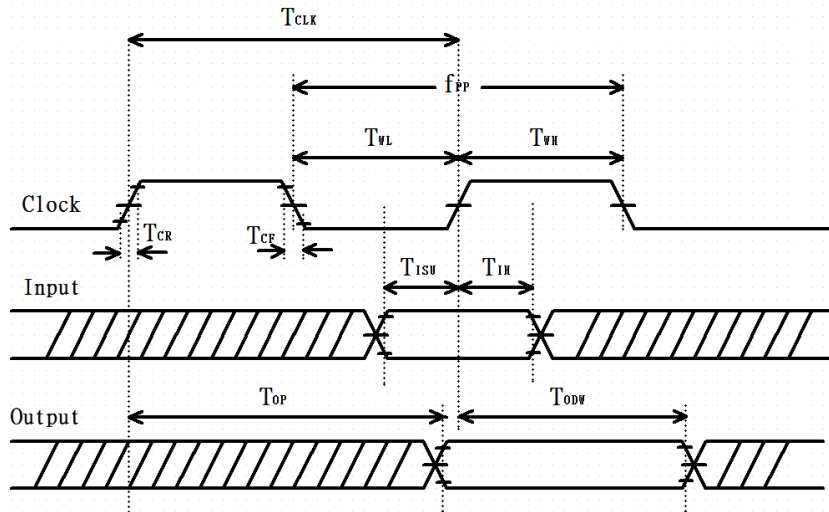


Figure 5: SDIO protocol timing Diagram--- SDR104 modes (up to 208 MHz) (1.8V)

Note: Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

Table 23: SDIO timing requirements--- SDR104 modes (up to 208MHz) (1.8V)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
fPP	Clock Frequency	SDR104	0	-	208	MHz
TISU	Input setup time	SDR104	1.4	--	-	ns
TIH	Input Hold time	SDR104	0.8	-	-	ns
TCLK	Clock Time	SDR104	4.8	-	-	ns
TCR, TCF	Raise time, Fall time TCR, TCF <0.96ns (max) at 208MHz CCARD=10pF	SDR104	-	-	0.2*TCLK	ns
TOP	Card Output phase	SDR104	0	-	10	ns
TODW	Output timing pf variable data window	SDR12/25/50	2.88	-	-	ns

10.1.4 SDR50 Mode (50MHz) (1.8V)

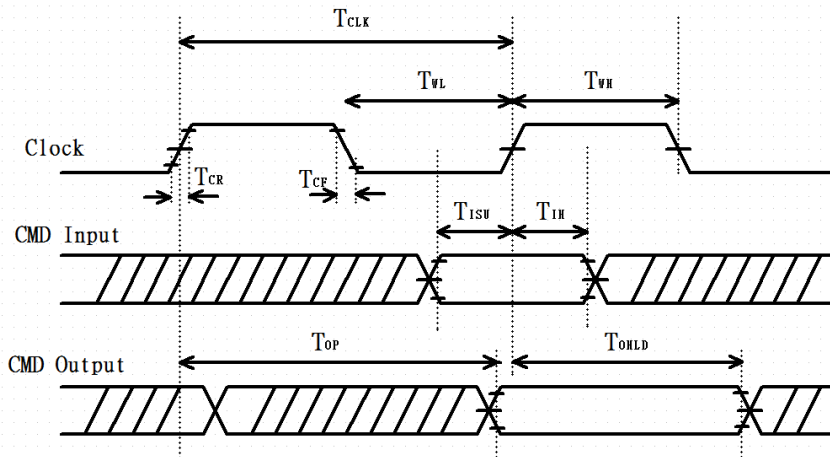


Figure 6: SDIO CMD timing diagram--- SDR50 modes (50 MHz) (1.8V)

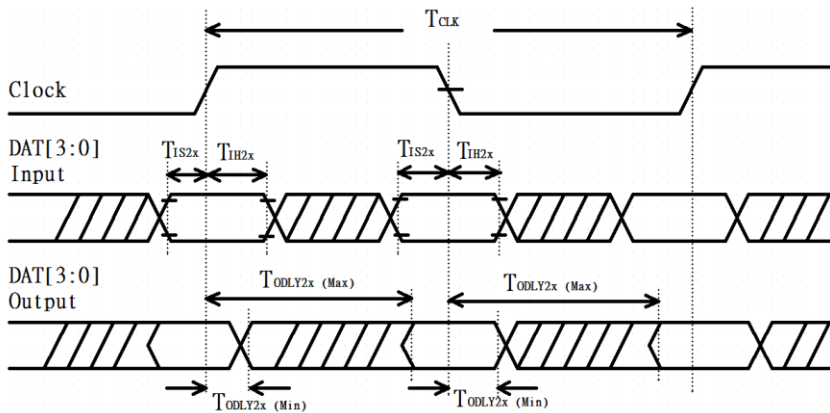


Figure 7: SDIO DAT[3:0] timing Diagram--- SDR50 modes (50 MHz) (1.8V)

Note: In SDR50 mode, DAT[3:0] lines are samples on both edges of the clock (not applicable for CMD line)

Table 24: SDIO timing requirements – SDR50 modes (50 MHz)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Clock						
TCLK	Clock time 50MHz (max) between rising edge	SDR50	20	--	--	ns
TCR, TCF	Rise time, fall time TCR, TCF < 4.00ns (max) at 50MHz. CCARD=10pF	SDR50	--	--	0.2*TCLK	ns
Clock Duty	--	SDR50	45	--	55	%
CMD Input (referenced to clock rising edge)						
TIS	Input setup time CCARD ≤ 10pF (1 card)	SDR50	6	--	--	ns
TIH	Input hold time CCARD ≤ 10pF (1 card)	SDR50	0.8	--	--	ns

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
CMD Output (referenced to clock rising and falling edge)						
TODLY	Output delay time during data transfer mode CL ≤ 30pF (1 card)	SDR50	--	--	13.7	ns
TOHLD	Output hold time CL ≥ 15pF (1 card)	SDR50	1.5	--	--	ns
DAT[3:0] Input (referenced to clock rising and falling edges)						
TIS2X	Input setup time CCARD ≤ 10pF (1 card)	SDR50	3	--	--	ns
TIH2X	Input hold time CCARD ≤ 10pF (1 card)	SDR50	0.8	--	--	ns
DAT[3:0] Output (referenced to clock rising and falling edges)						
TODLY2X (max)	Output delay time during data transfer mode CL ≤ 25pF (1 card)	SDR50	--	--	7.0	ns
TODLY2X (min)	Output hold time CL ≥ 15pF (1 card))	SDR50	1.5	--	--	ns

10.2 USB Specifications

The LWB5+ M.2 module can be powered through the USB interface and an external regulator is required to convert a 3.3V voltage for the LWB5+ M.2 module.

The LWB5+ M.2 module shared USB2.0 interface between WLAN and Bluetooth. The data bus DP/DM as USB signaling, the [Figure 8](#) shows the WLAN/Bluetooth shared the USB interface timing

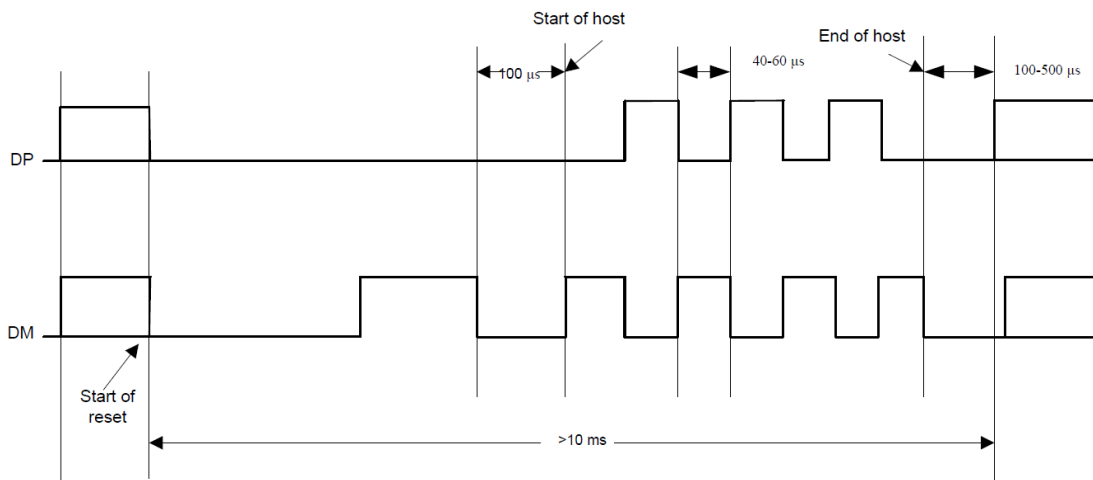


Figure 8: WLAN/Bluetooth USB Timing

10.3 PCM Interface Specifications

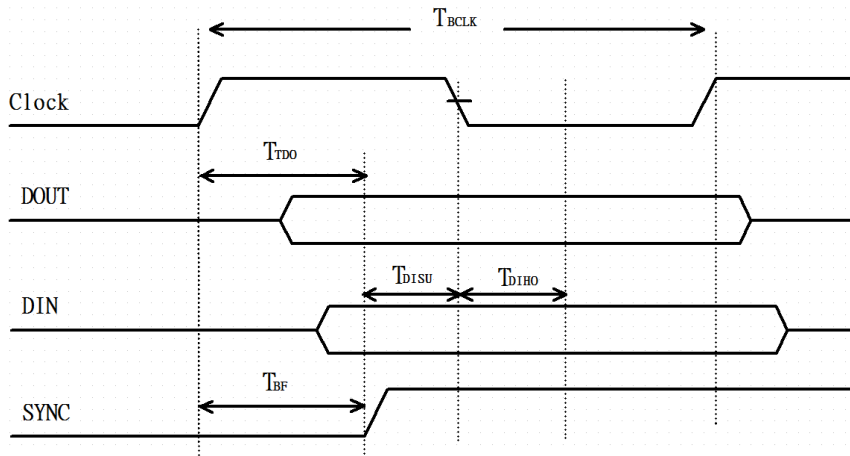


Figure 9: PCM Timing Specification – Master Mode

Table 25: PCM Timing Specification – Master Mode

Symbol	Parameter	Min.	Typ.	Max.	Unit
FBCLK	-	-	2/2.048	-	MHz
Duty Cycle _{BCLK}	-	0.4	0.5	0.6	-
T _{BCLK} rise/fall	-	-	3	-	ns
T _{D0}	-	-	-	15	ns
T _{DISU}	-	20	-	-	ns
T _{DIHO}	-	15	-	-	ns
T _{BF}	-	-	-	15	ns

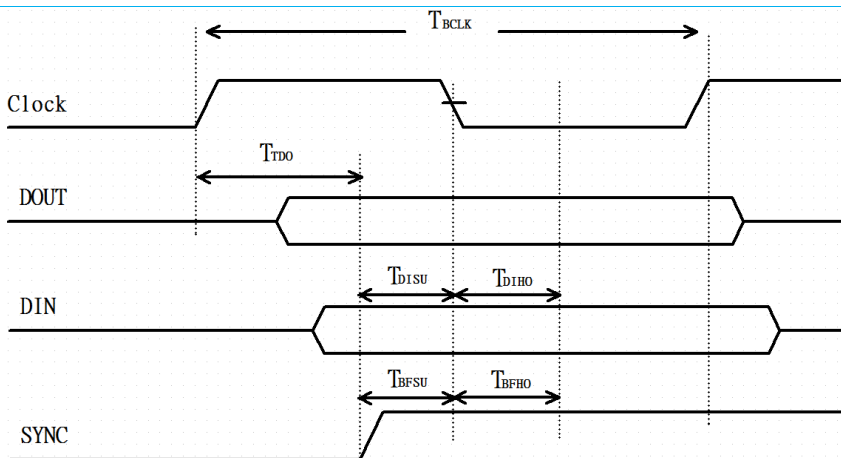


Figure 8: PCM Timing Specification – Slave Mode

Table 26: PCM Timing Specification – Slave Mode

Symbol	Parameter	Min.	Typ.	Max.	Unit
FBCLK	-	-	2/2.048	-	MHz
Duty Cycle _{BCLK}	-	0.4	0.5	0.6	-
T _{BCLK} rise/fall	-	-	3	-	ns

Symbol	Parameter	Min.	Typ.	Max.	Unit
TDO	-	-	-	30	ns
TDISU	-	15	-	-	ns
TDIHO	-	10	-	-	ns
TBFSU	-	15	-	-	ns
TBFHO	-	10	-	-	ns

11 POWER-UP SEQUENCE AND TIMING REQUIREMENT

11.1 Description on Control Signal

- **WL_REG_ON** – Used by the PMU to power-up the WLAN section. When this pin is high, the regulators are enabled and the WLAN section is out of reset. When this pin is low the WLAN section is in reset. If both the BT_REG_ON and WL_REG_ON pins are low, the regulators are disabled.
- **BT_REG_ON** – Used by the PMU (OR-gated with WL_REG_ON) to power-up the internal regulators. If both the BT_REG_ON and WL_REG_ON pins are low, the regulators are disabled. When this pin is low and WL_REG_ON is high, the BT section is in reset.

Notes:

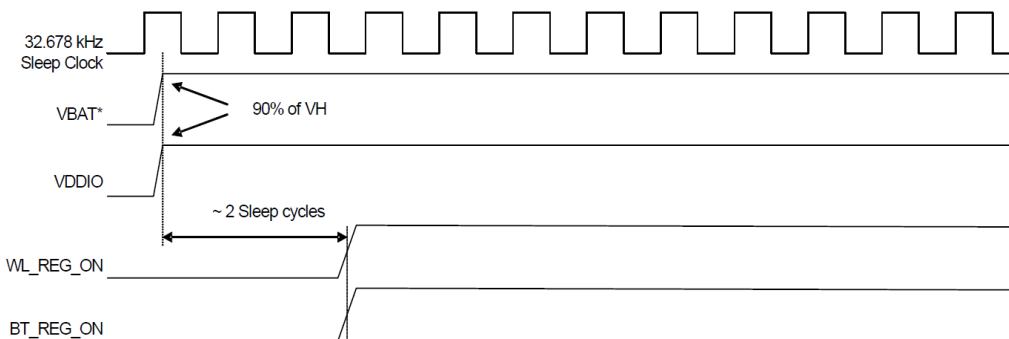
For both the WL_REG_ON and BT_REG_ON pins, there should be at least a 10-millisecond time delay between consecutive toggles (where both signals have been driven low). This allows time for the internal regulator to discharge. If this delay is not followed, there may be a VDDIO in-rush current on the order of 36 mA during the next PMU cold start.

The CYW4373E has an internal power-on reset (POR) circuit. The device is held in reset for a maximum of 110 milliseconds after VDDC and VDDIO have passed the POR threshold. Wait at least 150 milliseconds after VDDC and VDDIO are available before initiating SDIO accesses.

VBAT should not rise 10%–90% faster than 40 microseconds. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.

11.2 Control and Timing Diagrams

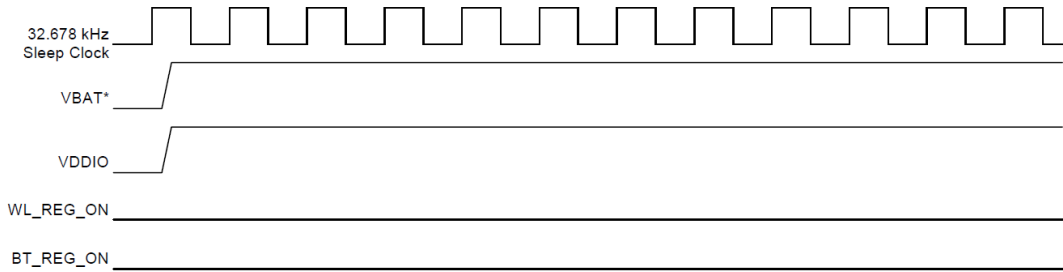
- **WLAN=ON; Bluetooth=ON**



***Notes:**

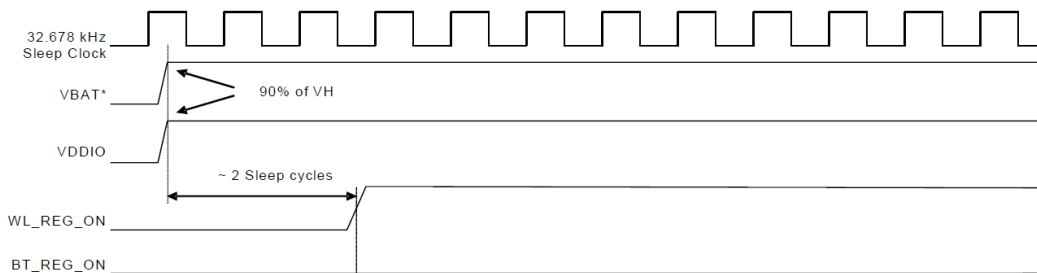
1. VBAT should not rise 10%–90% faster than 40 microseconds.
2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.

▪ **WLAN=OFF; Bluetooth=OFF**



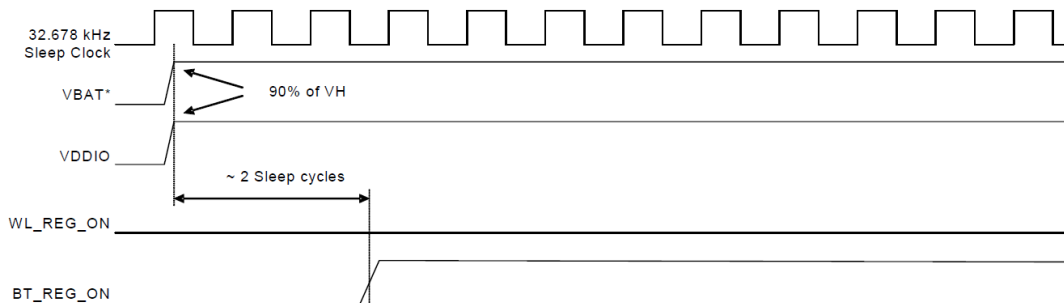
- *Notes:**
1. VBAT should not rise 10%–90% faster than 40 microseconds.
 2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.

▪ **WLAN=ON; Bluetooth=OFF**



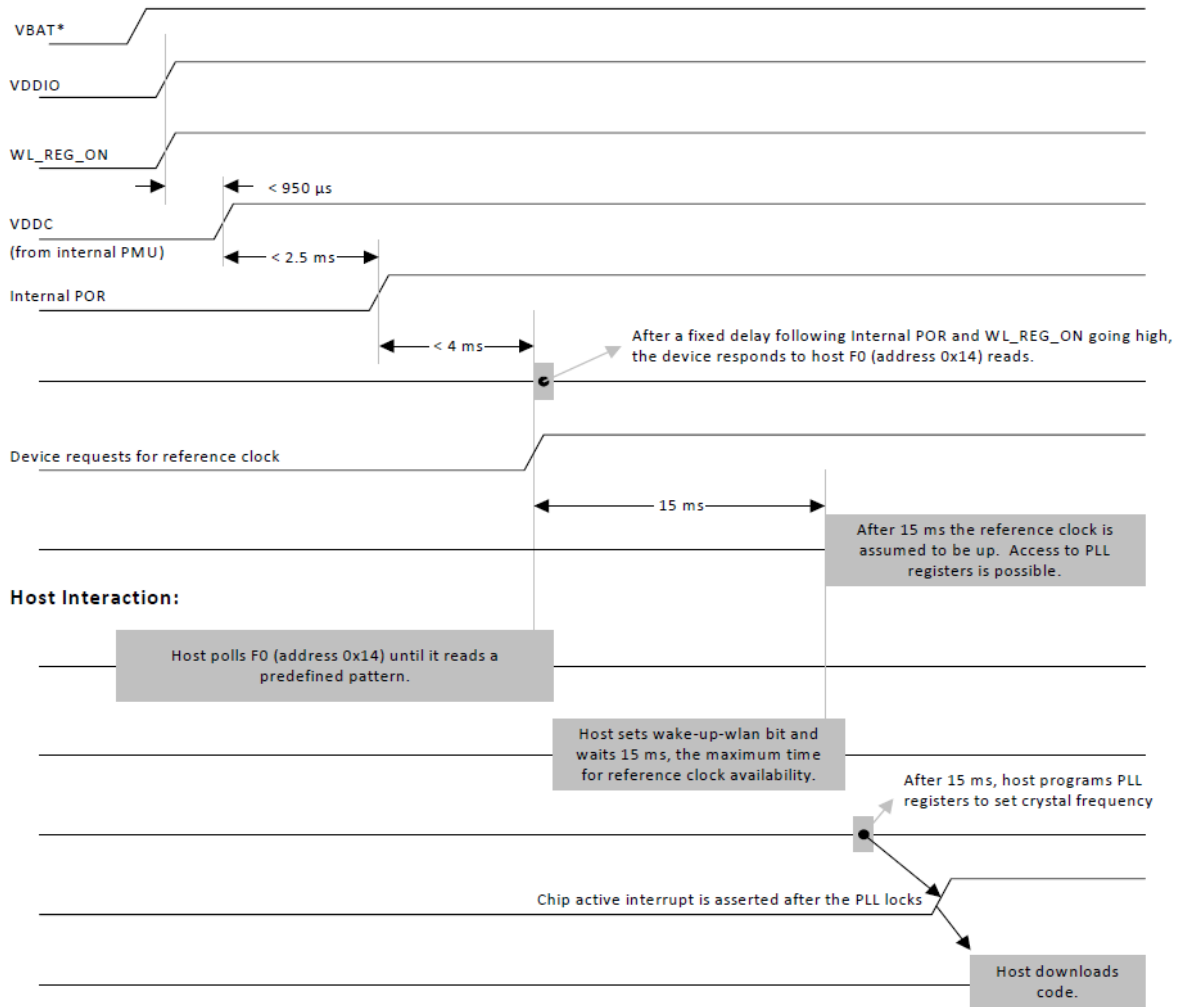
- *Notes:**
1. VBAT should not rise 10%–90% faster than 40 microseconds.
 2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.

▪ **WLAN=OFF; Bluetooth=ON**



- *Notes:**
1. VBAT should not rise 10%–90% faster than 40 microseconds.
 2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.

▪ WLAN Boot up Sequence for SDIO Host



*Notes:

1. VBAT and VDDIO should not rise 10%–90% faster than 40 microseconds.
2. VBAT should be up before or at the same time as VDDIO. VDDIO should NOT be present first or be held high before VBAT is high.

12 PIN DEFINITIONS

Table 27: Pin definitions of LWB5+ M.2 module

Pin #	Name	Type	Voltage Ref.	Function	If Not Used
1	GND	-	-	Ground	GND
2	3.3V	PWR I/P	3.3V	DC supply voltage for module. Operational is 3.2V to 3.6V (--
3	USB_D+	I/O	-	Data plus of shared USB 2.0 port	NC
4	3.3V	PWR I/P	3.3V	DC supply voltage for module. Operational is 3.2V to 3.6V	--
5	USB_D-	I/O	-	Data minus of shared USB 2.0 port	NC
6	LED1#	O	3.3V	Reserved	NC
7	GND	-	-	Ground	GND
8	PCM_CLK	I/O	1.8V	PCM clock. Can be master (Output) or slave (Input)	NC
9	SDIO CLK	I	1.8V	SDIO clock input	NC
10	PCM_SYNC	I/O	1.8V	PCM Sync. Can be master (Output) or slave (Input); Or SLIM bus data.	NC
11	SDIO CMD	I/O	1.8V	SDIO command line	NC
12	PCM_OUT	O	1.8V	PCM data output.	NC
13	SDIO DATA0	I/O	1.8V	SDIO data lin0	NC
14	PCM_IN	I	1.8V	PCM data input.	NC
15	SDIO DATA1	I/O	1.8V	SDIO data lin1	NC
16	LED2#	O	3.3V	Reserved	NC
17	SDIO DATA2	I/O	1.8V	SDIO data lin2	NC
18	GND	-	-	Ground	GND
19	SDIO DATA3	I/O	1.8V	SDIO data lin3	NC
20	UART WAKE#	O	1.8V	Reserved for feature support BT_HOST_WAKE. Output signal to wake up Host.	NC
21	SDIO WAKE#	I	1.8V	Reserved for feature support Reserved for WL_HOST_WAKE. Output signal to wake up host.	NC
22	UART_TXD	O	1.8V	Serial data output for the HCI UART interface.	NC
23	SDIO RESET#	-	-	NC	NC

Pin #	Name	Type	Voltage Ref.	Function	If Not Used
32	UART_RXD	I	1.8V	Serial data input for the HCI UART interface.	NC
33	GND	-	-	Ground	GND
34	UART_RTS	O	1.8V	Active-Low request-to-send signal for the HCI UART interface.	NC
35	PERp0	-	-	NC	NC
36	UART_CTS	I	1.8V	Active-Low clear-to-send signal for the HCI UART interface.	NC
37	PERn0	-	-	NC	NC
38	VENDER DEFINED38	-	-	NC	NC
39	GND	-	-	Ground	GND
40	VENDER DEFINED40	I	1.8V	Reserved for feature support BT_DEVICE_WAKE. Input signal from Host.	NC
41	PETp0	-	-	NC	NC
42	VENDER DEFINED42	I/O	1.8V	Reserved for feature support Reserved for WL_DEVICE_WAKE. Input from Host to wake up WLAN module.	NC
43	PETn0	-	-	NC	NC
44	COEX3	-	-	NC	NC
45	GND	-	-	Ground	GND
46	COEX2	I/O	1.8V	Reserved for feature support WCI-2 LTE coexistence Interface	NC
47	REFCLKp0	-	-	NC	NC
48	COEX1	I/O	1.8V	Reserved for feature support WCI-2 LTE coexistence Interface	NC
49	REFCLKn0	-	-	NC	NC
50	SUSCLK	I	-	External Sleep Clock input (32.768KHz) The sleep clock is always needed for using this module	--
51	GND	-	-	Ground	GND
52	PERST0#	-	-	NC	NC
53	CLKREQ0#	-	-	NC	NC
54	W_DISABLE2#	I	3.3V	Enables BT regulators. Internal 10K pull-up to enable BT by default. Ground to disable BT.	NC
55	PEWAKE0#	-	-	NC	NC
56	W_DISABLE1#	I	3.3 V	Enables WLAN regulators. Internal 10K pull-up to enable WLAN by default. Ground to disable WLAN.	NC
57	GND	-	-	Ground	GND
58	I2C DATA	-	-	NC	NC
59	RESERVED	-	-	NC	NC

Pin #	Name	Type	Voltage Ref.	Function	If Not Used
60	I2C CLK	-	-	NC	NC
61	RESERVED	-	-	NC	NC
62	ALERT#	-	-	NC	NC
63	GND	-	-	Ground	GND
64	RESERVED	-	-	NC	NC
65	RESERVED	-	-	NC	NC
66	UIM_SWP	-	-	NC	NC
67	RESERVED	-	-	NC	NC
68	UIM_POWER_SNK	-	-	NC	NC
69	GND	-	-	Ground	GND
70	UIM_POWER_SRC	-	-	NC	NC
71	RESERVED	-	-	NC	NC
72	3.3V	PWR I/P	3.3V	DC supply voltage for module. Operational is 3.2V to 3.6V	--
73	RESERVED	-	-	NC	NC
74	3.3V	PWR I/P	3.3V	DC supply voltage for module. Operational is 3.2V to 3.6V	--
75	GND	-	-	Ground	GND

13 MECHANICAL SPECIFICATIONS

Module dimensions of LWB5+ M.2 module is 17 x 12 x 2.1 mm. Detailed drawings are shown in Figure 11.

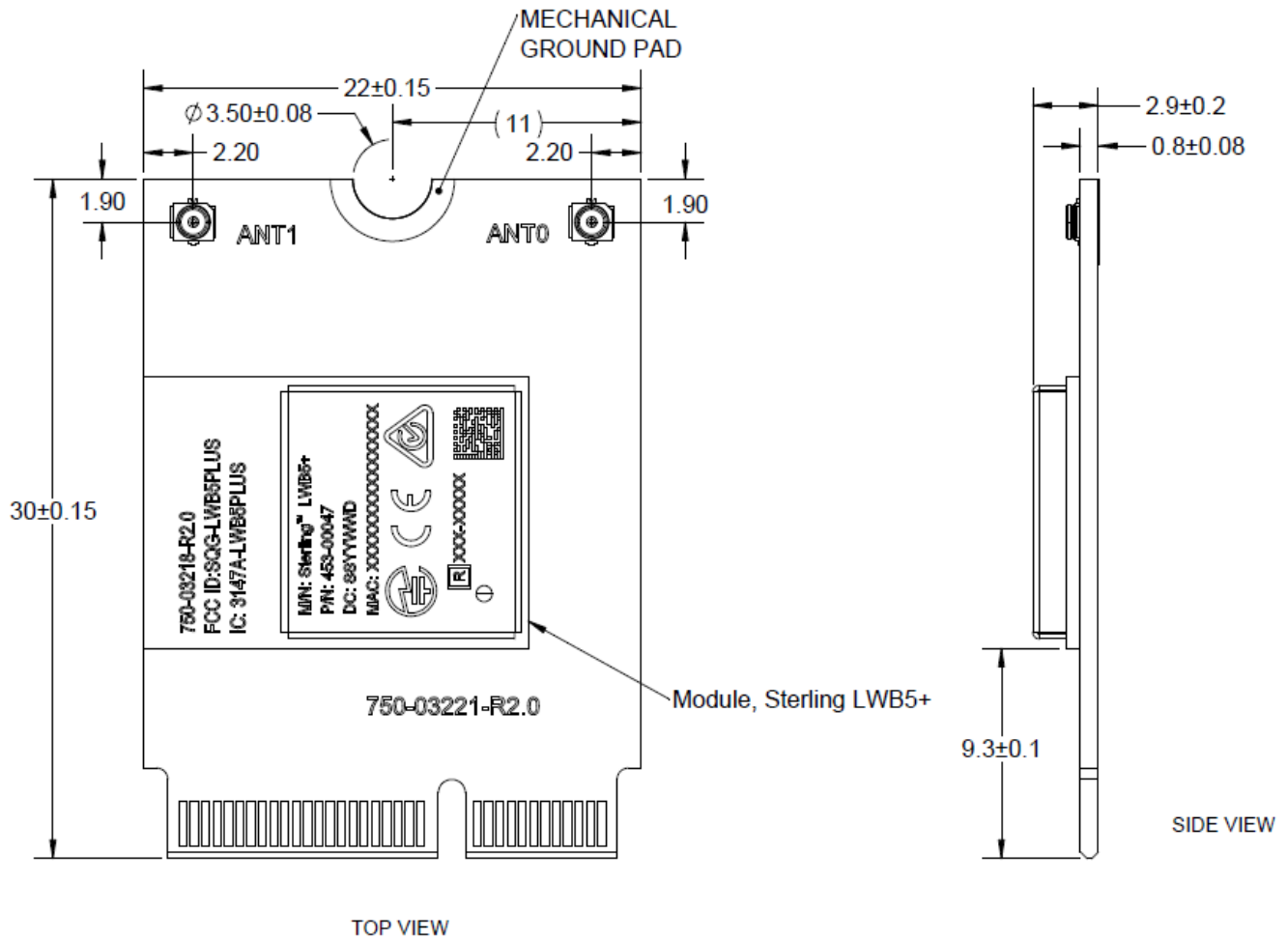


Figure 11: Mechanical drawing - LWB5+ M.2 module

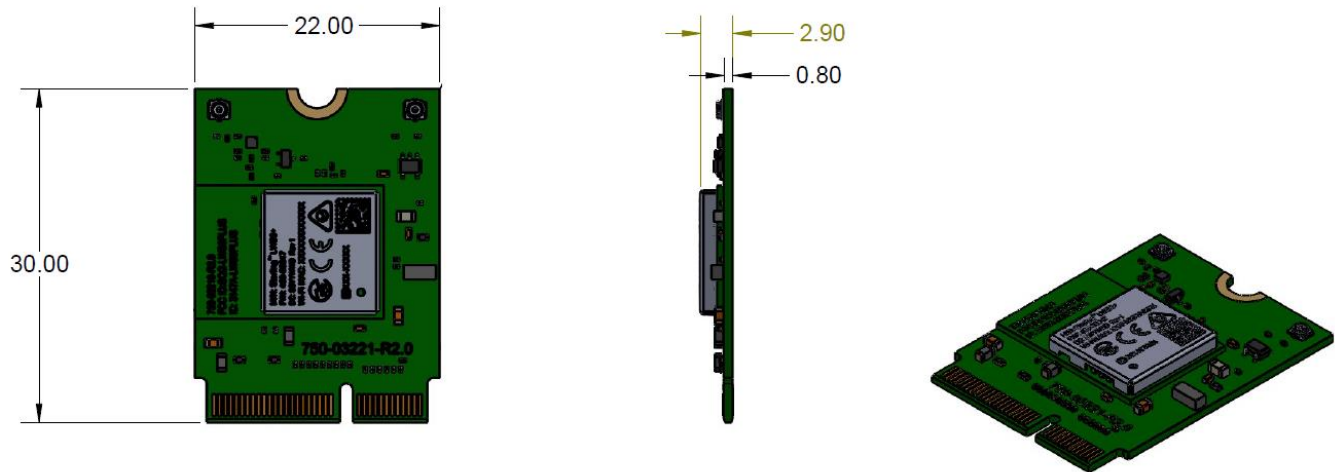


Figure 12: Module dimension of LWB5+ M.2 module – Top View

Note: The Wi-Fi MAC address is located on the product label.
The last digit of Wi-Fi MAC address is assigned to either 0, 2, 4, 6, 8, A, C, E.
The BT MAC address is the Wi-Fi MAC address plus 1.

14 MOUNTING

The LWB5+ M.2 module connects to the host via a standard PCI EXPRESS M2 connector. The Kyocera's (www.Kyocera-connector.com) 6411 series provide 1.8 mm, 2.3 mm and 3.2 mm connector heights and JAE's (<https://www.jae.com/en/>) SM3 series provide 1.2 mm, 2.15 mm, 3.1 mm and 4.1 mm connector heights.

Because the LWB5+ M.2 module is a single-side component module, we recommend the following part numbers which have 2.3 mm and 3.1 mm connector height):

M.2 Key-E Connector	Connector Height
KYOCERA 24-6411-067-101-894E	2.3 mm
JAE SM3ZS067U310AERxxxx	3.1 mm

The stand-off mating to the recommend 2.3 mm connector from EMI STOP (www.EMISTOP.com) is part number **F50M16-041525P1D4M** and 3.1mm from JAE (<https://www.jae.com/en/>) is part number **SM3ZS067U310-NUT1-Rxxxx**.

M.2 Key-E Connector	Stand-off
KYOCERA 24-6411-067-101-894E	EMI STOP F50M16-041525P1D4M
JAE SM3ZS067U310AERxxxx	JAE SM3ZS067U310-NUT1-Rxxxx

Detailed layout and stencil opening are show in [Figure 13](#).

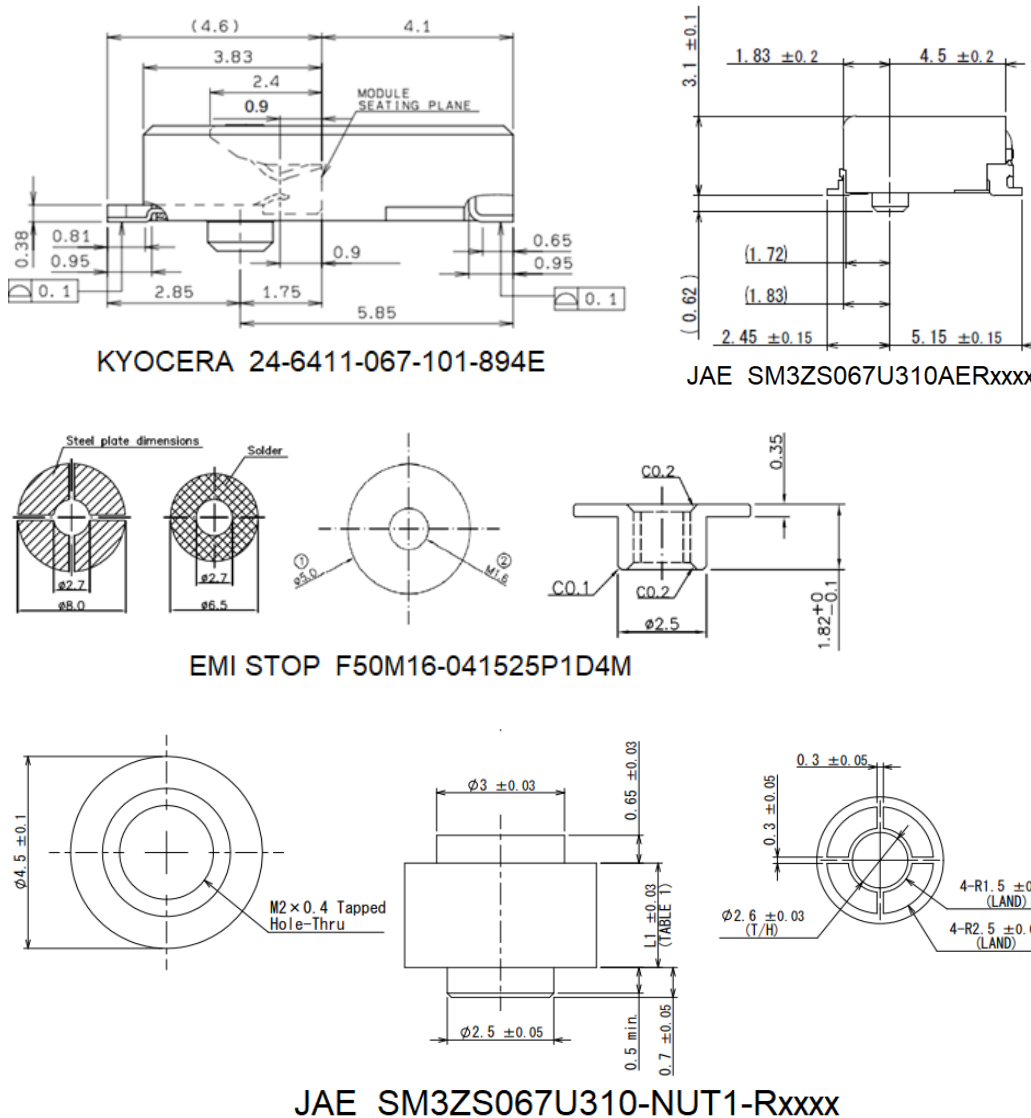


Figure 13: Mounting information of the LWB5+ M.2 module and recommended layout pattern for the stand-off

15 RF LAYOUT DESIGN GUIDELINES

The following is a list of RF layout design guidelines and recommendation when installing a Laird radio into your device.

- Do not run antenna cables directly above or directly below the radio.
- Do not place any parts or run any high-speed digital lines below the radio.
- If there are other radios or transmitters located on the device (such as a *Bluetooth* radio), place the devices as far apart from each other as possible. Also, make sure there is at least 25 dB isolation between these two antennas.
- Ensure that there is the maximum allowable spacing separating the antenna connectors on the Laird Connectivity radio from the antenna. In addition, do not place antennas directly above or directly below the radio.
- Laird Connectivity recommends the use of a double-shielded cable for the connection between the radio and the antenna elements.
- Be sure to put a 10uF capacitor on EACH 3.3V power pin. Also, place that capacitor to the pin as close as possible to make sure the internal PMU working correctly.
- Use proper electro-static-discharge (ESD) procedures when installing the Laird Connectivity radio module.
- To avoid negatively impacting Tx power and receiver sensitivity, do not cover the antennas with metallic objects or components.

15.1 Recommended and Required Storage/Handling Conditions

15.1.1 Prior to Opening the Dry Packing

The following are required storage conditions **prior to opening the dry packing**:

- Normal temperature: 5~40°C
- Normal humidity: 80% (Relative humidity) or less
- Storage period: One year or less

Note: Humidity means Relative Humidity.

15.1.2 After Opening the Dry Packing

The following are required storage conditions **after opening the dry packing** (to prevent moisture absorption):

- Storage conditions for one-time soldering:
 - Temperature: 5-25°C
 - Humidity: 60% or less
 - Period: 72 hours or less after opening
- Storage conditions for two-time soldering
 - Storage conditions following opening and prior to performing the 1st reflow:
 - Temperature: 5-25°C
 - Humidity: 60% or less
 - Period: A hours or less after opening
 - Storage conditions following completion of the 1st reflow and prior to performing the 2nd reflow
 - Temperature: 5-25°C
 - Humidity: 60% or less
 - Period: B hours or less after completion of the 1st reflow

Note: Should keep A+B within 72 hours.

15.1.3 Precautions for Use

- Opening/handling/removing must be done on an anti-ESD treated workbench. All workers must also have undergone anti-ESD treatment.
- The devices should be mounted within one year of the date of delivery.

16 PACKAGE

16.1 Shipping

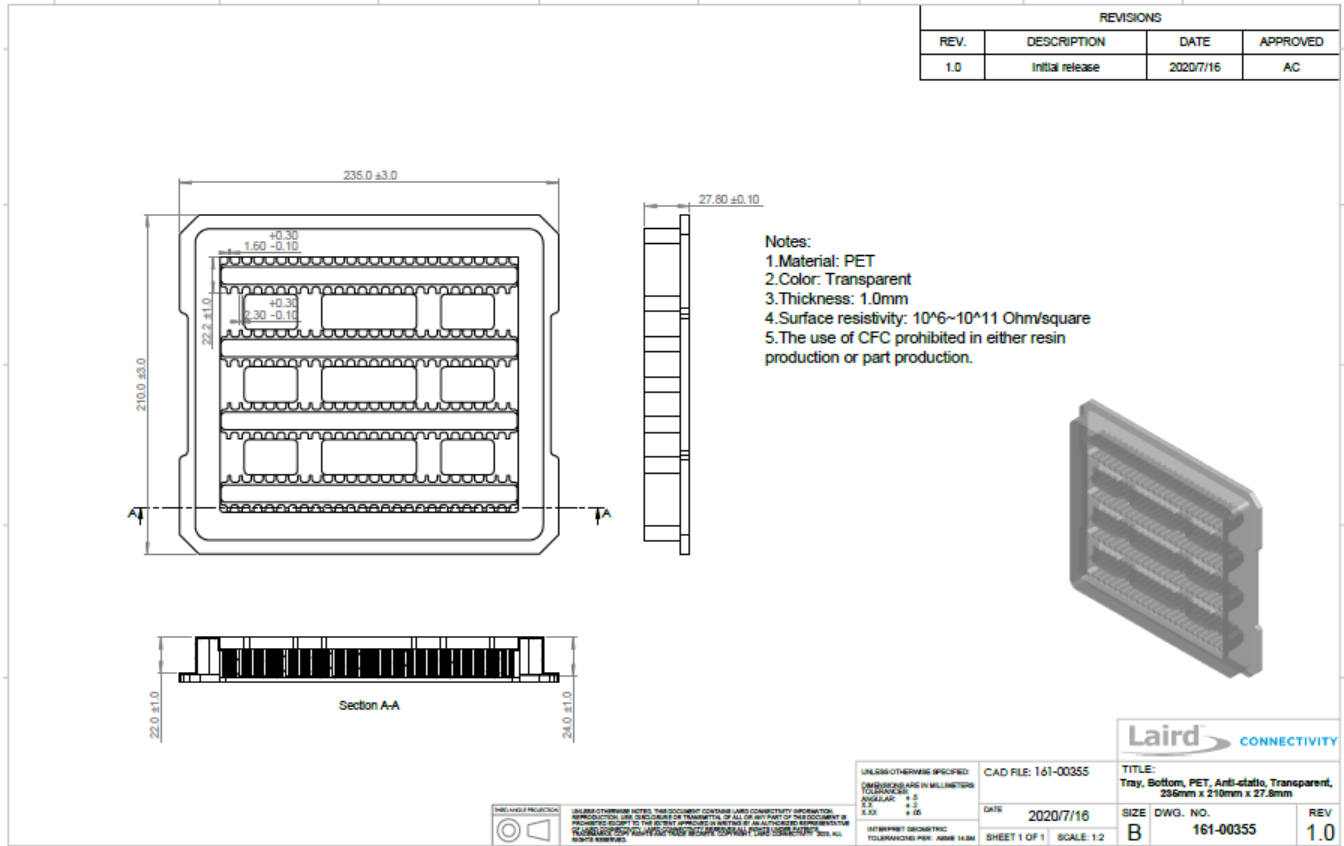


Figure 9: Shipping Tray, Bottom, 161-00355

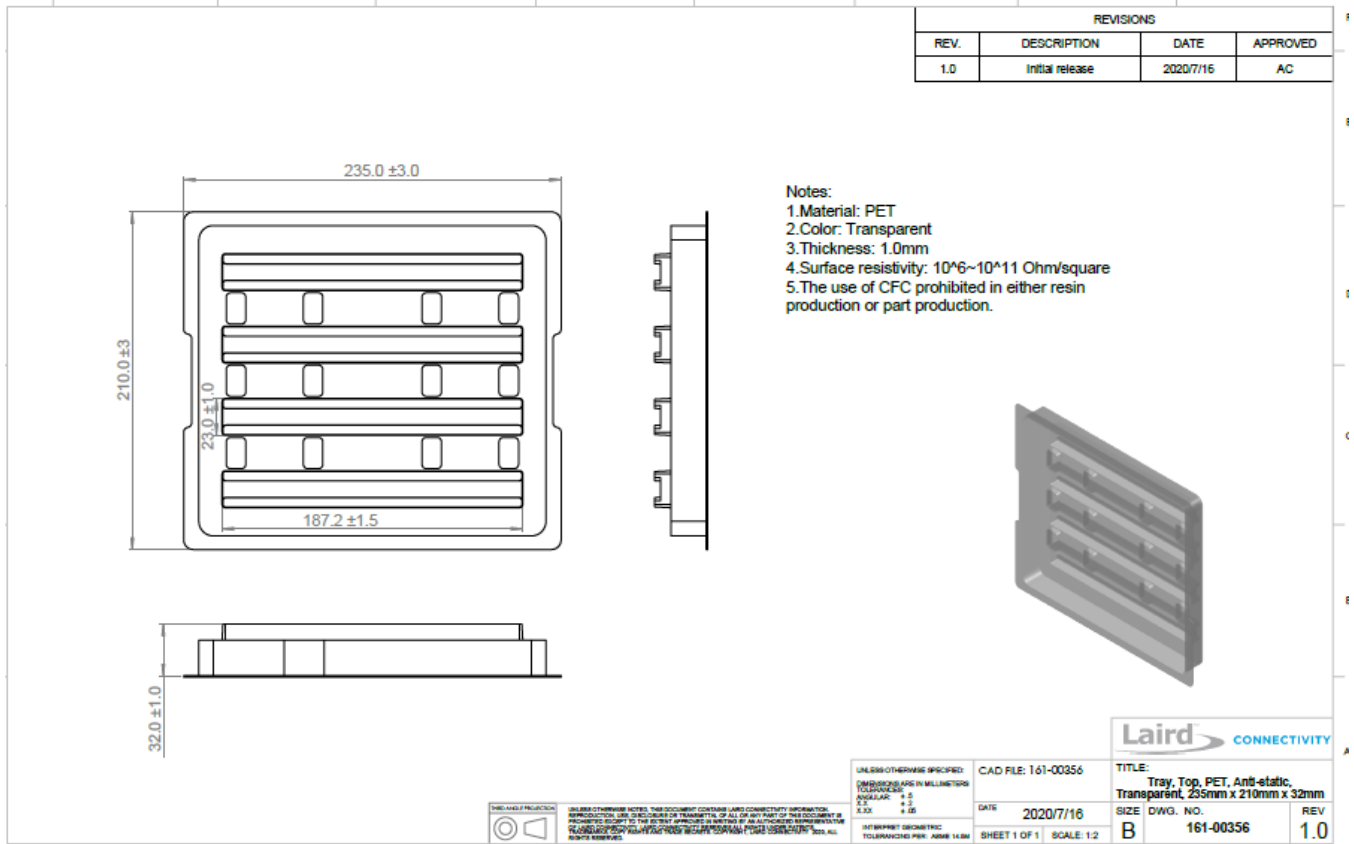


Figure 10: Shipping Tray, Top, 161-00356

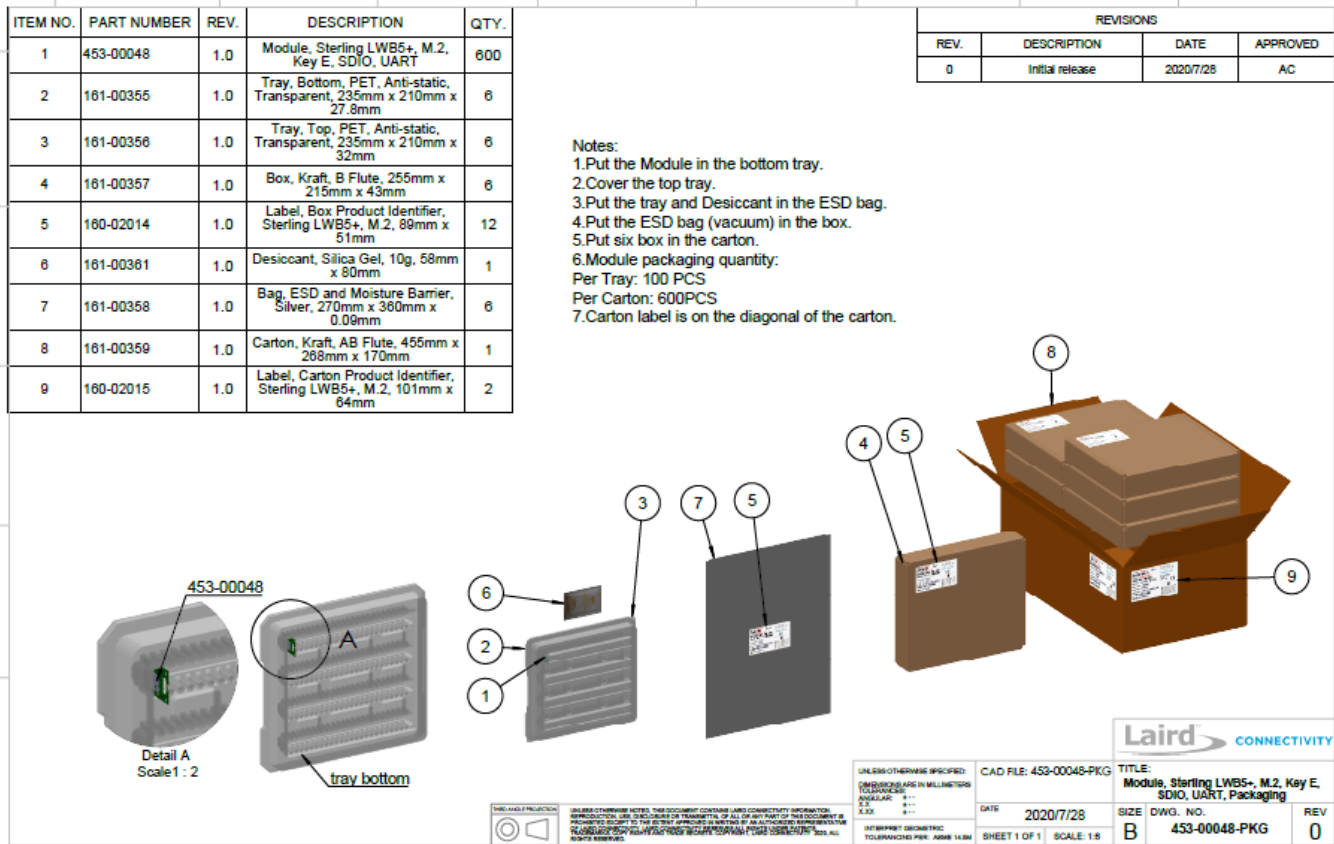


Figure 11: Sterling LWB5+ M.2 Packaging Process

16.2 Labelling

The following label is placed on the bag and the inner box.



Figure 12: Bag and Box Label

The following label is located on the adjacent sides of the master carton.



Figure 13: Master Carton Package Label

17 REGULATORY

Note: For complete regulatory information, refer to the [Sterling LWB5+ Regulatory Information](#) document which is also available from the [Sterling LWB5+ product page](#).

The Sterling LWB5+ holds current certifications in the following countries:

Country/Region	Regulatory ID
USA (FCC)	SQG-LWB5PLUS
EU	N/A
Canada (ISED)	3147A-LWB5PLUS
Japan (MIC)	201-200402
Australia	N/A
New Zealand	N/A

18 ORDERING INFORMATION

Part Number	Description
453-00048	1x1 802.11 a/b/g/n/ac + Bluetooth 5.2 SDIO/UART M.2 Module
453-00049	1x1 802.11 a/b/g/n/ac + Bluetooth 5.2 USB/USB M.2 Module
453-00048-K1	Development Kit for 1x1 802.11 a/b/g/n/ac + Bluetooth 5.2 SDIO/UART M.2 Module
453-00049-K1	Development Kit for 1x1 802.11 a/b/g/n/ac + Bluetooth 5.2 USB/USB M.2 Module

19 BLUETOOTH SIG QUALIFICATION

19.1 Overview

The Sterling LWB5+ Series module is listed on the Bluetooth SIG website as a qualified Controller Subsystem.

Design Name	Owner	Declaration ID	Link to listing on the SIG website
Sterling LWB5+	Laird Connectivity	D050832	https://launchstudio.bluetooth.com/ListingDetails/119009

It is a mandatory requirement of the Bluetooth Special Interest Group (SIG) that every product implementing Bluetooth technology has a Declaration ID. Every Bluetooth design is required to go through the qualification process, even when referencing a Bluetooth Design that already has its own Declaration ID. The Qualification Process requires each company to register as a member of the Bluetooth SIG – www.bluetooth.org

The following is a link to the Bluetooth Registration page: <https://www.bluetooth.org/login/register/>

For each Bluetooth Design, it is necessary to purchase a Declaration ID. This can be done before starting the new qualification, either through invoicing or credit card payment. The fees for the Declaration ID will depend on your membership status, please refer to the following webpage:

<https://www.bluetooth.org/en-us/test-qualification/qualification-overview/fees>

For a detailed procedure of how to obtain a new Declaration ID for your design, please refer to the following SIG document, (login is required to view this document):

https://www.bluetooth.org/DocMan/handlers/DownloadDoc.ashx?doc_id=283698&vId=317486

19.2 Qualification Steps When Referencing a Laird Controller Subsystem Design

To qualify your product when referencing a Laird Controller Subsystem design, follow these steps:

1. To start a listing, go to: https://www.bluetooth.org/tpg/QLI_SDoc.cfm

Note: A user name and password are required to access this site.

2. In step 1, select the option, New Listing and Reference a Qualified Design.
3. Enter D050382 in the Controller Subsystem table entry.
4. Enter your complimentary Host Subsystem and optional Profile Subsystem QDID in the table entry.
5. Select your pre-paid Declaration ID from the drop-down menu or go to the Purchase Declaration ID page.

Note: Unless the Declaration ID is pre-paid or purchased with a credit card, you cannot proceed until the SIG invoice is paid.

6. Once all the relevant sections of step 1 are finished, complete steps 2, 3, and 4 as described in the help document accessible from the site.

Your new design will be listed on the SIG website and you can print your Certificate and DoC.

For further information please refer to the following training material:

<https://www.bluetooth.org/en-us/test-qualification/qualification-overview/listing-process-updates>

If you require assistance with the qualification process please contact our recommended Bluetooth Qualification Expert (BQE), Steve Flooks, steve.flooks@eurexuk.com

20 ADDITIONAL ASSISTANCE

Please contact your local sales representative or our support team for further assistance:

Laird Connectivity

Support Centre: <https://www.lairdconnect.com/resources/support>

Email: wireless.support@lairdconnectivity.com

Phone: Americas: +1-800-492-2320

Europe: +44-1628-858-940

Hong Kong: +852 2923 0610

Web: <https://www.lairdconnect.com/products>

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